

# **RX Family**

# Clock Synchronous Control Module for Serial NOR Flash Memory Access

#### Introduction

This application note explains how to control and use serial flash memory with microcontrollers manufactured by Renesas Electronics. Refer to "Target Devices" below for a list of the supported serial flash memory products.

The control software accompanying this application note is upper-layer software that controls the serial flash memory as a slave device.

Lower-layer software (clock synchronous single master control software) for controlling the SPI mode on the individual microcontroller, operating as a master device, is available separately; it can be obtained from the webpage below. Note that although the clock synchronous single master control software may support newer microcontrollers, there may be cases where the control software presented in this application note has not yet been updated to match. For information on the latest supported microcontrollers and matching control software releases, see the "Clock Synchronous Single Master Control Software (Lower-level layer of the software)" section of the following webpage:

Serial Flash Memory Driver

http://www.renesas.com/driver/spi serial flash

The control software uses Firmware Integration Technology (FIT). It is referred to as the serial flash memory FIT module in the documentation of development tools with FIT support. Other similar function control modules using FIT are referred to as FIT modules or as "function name" FIT modules.

When using development tools that do not support FIT, the software code can be imported with the FIT functionality disabled.

# **Target Devices**

Device on which operation has been confirmed:

Serial NOR flash memory

Macronix International Co., Ltd.

- MX25/66L family serial NOR flash memory 32Mbit 1Gbit
- MX25R family serial NOR flash memory 64Mbit

Dialog Semiconductor Plc.

AT25QF family serial NOR flash memory 64Mbit

RX Family microcontrollers

Microcontrollers on which operation has been confirmed:

RX111, RX110, RX113 and RX130 Group (RSPI)

RX230, RX231, RX23T and RX24T Group (RSPI)

RX64M and RX71M Group (RSPI, QSPI, SCI)

RX72T and RX72N Group (RSPI, SCI)

RX671 Group (QSPIX, RSCI)

When applying the information in this application note to a microcontroller other than the above, modifications should be made as appropriate to match the specification of the microcontroller and careful evaluation performed.

The following abbreviations are used in this application note:



- Single-SPI (communication in single-SPI mode)
- Dual-SPI (communication in dual-SPI mode)
- Quad SPI (communication in quad-SPI mode)

# **Target Compilers**

- Renesas Electronics C/C++ Compiler Package for RX Family
- GCC for Renesas RX
- IAR C/C++ Compiler for Renesas RX

For details of the confirmed operation contents of each compiler, refer to "5.1 Confirmed Operation Environment".

### **FIT Related Documents**

- Firmware Integration Technology User's Manual (R01AN1833)
- RX Family Board Support Package Module Using Firmware Integration Technology (R01AN1685)



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# 1. Overview

This software controls serial flash memory, using a Renesas microcontroller.

A clock synchronous single master control software specific to the microcontroller model used (available separately) is required.

Table 1.1 lists the peripheral devices used and their applications, and figure 1.1 shows a usage example.

The functions of the module are described briefly below.

- Block type device driver using the Renesas microcontroller as the master device and the serial flash memory as the slave device
- Control in SPI mode of target serial communication FIT module, using the microcontroller's built-in serial communication functionality (clock synchronous mode) (See 1.3.1, FIT Module–Related Application Notes.)
  - RSPI FIT module
  - QSPI FIT module
  - SCI FIT module
  - QSPIX FIT module
  - RSCI FIT module
- Ability to control up to two serial flash memory devices
- Ability to make serial flash memory settings on a per-device basis
- Support for both big-endian and little-endian byte order

Table 1.1 Peripheral Devices Used and Their Uses

Peripheral Device	Use
Microcontroller's on-chip serial communication function (clock synchronous mode)	Communication with SPI slave device using serial communication functionality (clock synchronous mode): Single or multiple channels (required)
Port	For slave device selection control signals: A number of ports equal to the number of devices used are necessary (required).

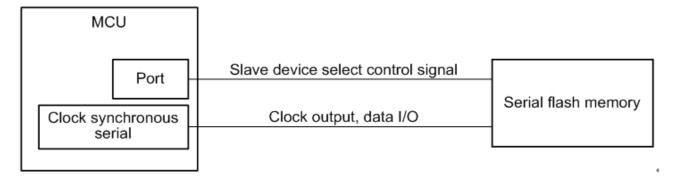


Figure 1.1 Sample Configuration

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# 1.1 FIT Support of Serial flash Memory Control Software

The serial flash memory control software can be combined with other FIT modules, allowing easy integration into your project.

The serial flash memory control software can also be integrated into your project as an API. For information on adding the serial flash memory control software, see 2.10, Adding the Driver to Your Project.

#### 1.2 Overview of APIs

Table 1.2 lists the API functions of the serial flash memory control software.

Table 1.2 API Functions

Function Name	Description	
R_FLASH_SPI_Open()	Control software initialization processing	
R_FLASH_SPI_Close()	Control software end processing	
R_FLASH_SPI_Read_Status()	Status Register read processing	
R_FLASH_SPI_Read_Status2()	Status Register 2 read processing	
R_FLASH_SPI_Read_Status3()	Status Register 3 read processing	
R_FLASH_SPI_Set_Write_Protect()	Write protect setting processing	
R_FLASH_SPI_Write_Di()	WRDI command processing	
R_FLASH_SPI_Read_Data()*1	Data read processing	
R_FLASH_SPI_Write_Data_Page()*1	Data write (Single-page write) processing	
R_FLASH_SPI_Erase()	Erase processing	
R_FLASH_SPI_Polling()	Polling processing	
R_FLASH_SPI_Read_ID()	ID read processing	
R_FLASH_SPI_GetMemoryInfo()	Memory size acquisition processing	
R_FLASH_SPI_Read_Configuration()	Configuration Register read processing	
R_FLASH_SPI_Write_Configuration()	Configuration Register write processing	
R_FLASH_SPI_Write_Status()	Status Register 1 write processing	
R_FLASH_SPI_Write_Status2()	Status Register 2 write processing	
R_FLASH_SPI_Write_Status3()	Status Register 3 write processing	
R_FLASH_SPI_Set_4byte_Address_Mode()	4-byte address mode setting processing	
R_FLASH_SPI_Read_Security()	Security register read processing	
R_FLASH_SPI_Read_Data_Security_Page()	Data Security Page read processing	
R_FLASH_SPI_Write_Data_Security_Page()	Data Security Page write processing	
R_FLASH_SPI_Quad_Enable()	Quad mode enable setting processing	
R_FLASH_SPI_Quad_Disable()	Quad mode disable setting processing	
R_FLASH_SPI_GetVersion()	Control software version information acquisition processing	
R_FLASH_SPI_Set_LogHdlAddress()	LONGQ FIT module handler address setting processing	
R_FLASH_SPI_Log()	Error log acquisition processing using LONGQ FIT module	
R_FLASH_SPI_1ms_Interval()*2	Clock synchronous single master control software interval	
	timer counter processing	

- Notes: 1. To speed up data transfers, align the start address with a 4-byte boundary when specifying transmit and receive data storage buffer pointers. There is a limitation on the data size when using DMAC transfer or DTC transfer. Refer to the documentation of the clock synchronous single master control software for the microcontroller used regarding the allowable data size setting range.
  - 2. This function must be called at 1 ms intervals, using a hardware or software timer, in order to implement timeout detection when using DMAC transfer or DTC transfer.

# 1.3 Related Application Notes

Application notes related to the serial flash memory control software are listed below. Refer to them alongside this application note.

# 1.3.1 FIT Module-Related Application Notes

- RX Family RSPI Module Using Firmware Integration Technology(R01AN1827)
- RX Family QSPI Clock Synchronous Single Master Control Module Using Firmware Integration Technology(R01AN1940)
- RX Family Application Note SCI Multi-Mode Module Using Firmware Integration Technology(R01AN1815)
- RX Family QSPIX Module Using Firmware Integration Technology(R01AN5685)
- RX Family RSCI Module Using Firmware Integration Technology(R01AN5759)
- RX Family DMAC Module Using Firmware Integration Technology(R01AN2063)
- RX Family DTC Module Using Firmware Integration Technology(R01AN1819)
- RX Family CMT Module Using Firmware Integration Technology(R01AN1856)
- RX Family GPIO Module Using Firmware Integration Technology(R01AN1721)
- RX Family MPC Module Using Firmware Integration Technology(R01AN1724)
- RX Family LONGQ Module Using Firmware Integration Technology(R01AN1889)
- RX Family Clock Synchronous Control Module for EEPROM Access Firmware Integration Technology(R01AN2325)
- RX Family Memory Access Driver Interface Module Using Firmware Integration Technology(R01AN4548)

# 1.4 Using Serial Flash Memory Module

# 1.4.1 Using Serial Flash Memory Module in C++ project

```
For C++ project, add Serial Flash Memory Module header file within extern "C"{}: extern "C" {
    #include "r_smc_entry.h"
    #include "r_flash_spi_if.h"
}
```

# 1.5 Hardware Settings

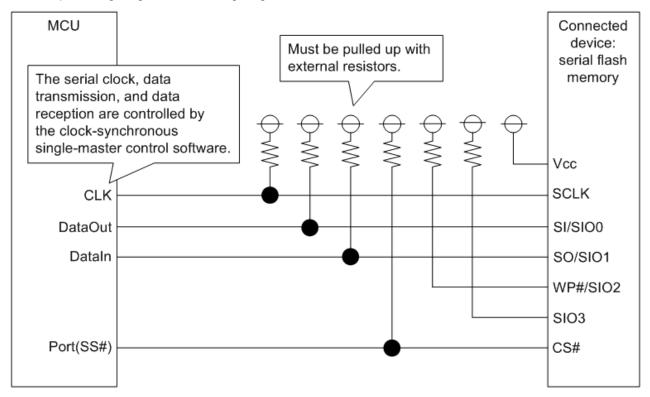
# 1.5.1 Hardware Configuration Example

Figure 1.2 is a connection diagram. The pin names differ according to the microcontroller and serial interface used. Refer to the listing of pins and functions in table 1.3 and assign pins on the specific microcontroller used.

To achieve high-speed operation, consider adding damping resistors or capacitors to improve the circuit matching of the various signal lines.

## (1) Single-SPI Configuration Example

An example wiring diagram when using single-SPI is shown below.



- The names of the pins used by the microcontroller for serial I/O depend on the microcontroller version.
- In the example WP# and RESET# are not used. When using WP# and RESET#, be sure to check the specifications of the device to be used.

Figure 1.2 Sample Wiring Diagram for MCU and SPI Slave Device Using Single-SPI

Table 1.3 Single-SPI Pins Used and Functions

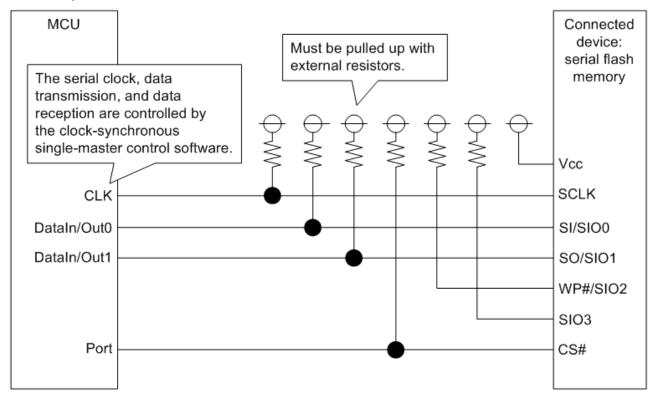
Pin Name	I/O	Description
CLK	Output	Clock output
DataOut	Output	Master data output
DataIn	Input	Master data input
Port (Port (SS#) of figure 1.2)	Output	Slave device select (SS#) output

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# (2) Dual-SPI Configuration Example

An example wiring diagram when using dual-SPI is shown below.

In order to use dual-SPI the target microcontroller must be equipped with quad serial peripheral interface functionality.



- The names of the pins used by the microcontroller for serial I/O depend on the microcontroller version.
- In the example WP# and RESET# are not used. When using WP# and RESET#, be sure to check the specifications of the device to be used.

Figure 1.3 Sample Wiring Diagram for MCU and SPI Slave Device Using Dual-SPI

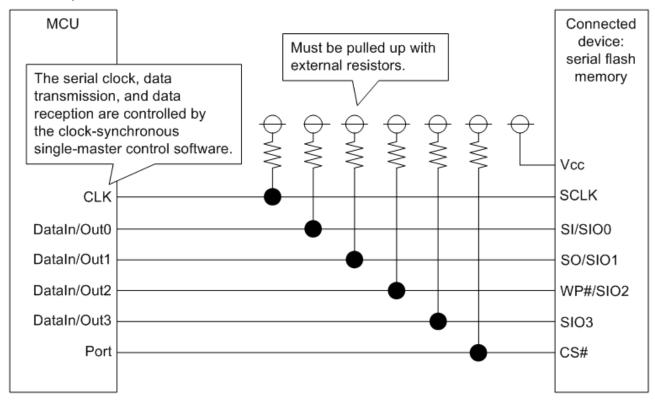
Table 1.4 Dual-SPI Pins Used and Functions

Pin Name	I/O	Description
CLK	Output	Clock output
DataIn/Out0	I/O	Master data I/O 0
DataIn/Out1	I/O	Master data I/O 1
Port (Port (SS#) of figure 1.3)	Output	Slave device select (SS#) output

# (3) Quad-SPI Configuration Example

An example wiring diagram when using quad-SPI is shown below.

In order to use quad-SPI the target microcontroller must be equipped with quad serial peripheral interface functionality.



- The names of the pins used by the microcontroller for serial I/O depend on the microcontroller version.
- In the example WP# and RESET# are not used. When using WP# and RESET#, be sure to check the specifications of the device to be used.

Figure 1.4 Sample Wiring Diagram for MCU and SPI Slave Device Using Quad-SPI

Table 1.5 Quad-SPI Pins Used and Functions

Pin Name	I/O	Description
CLK	Output	Clock output
DataIn/Out0	I/O	Master data I/O 0
DataIn/Out1	I/O	Master data I/O 1
DataIn/Out2	I/O	Master data I/O 2
DataIn/Out3	I/O	Master data I/O 3
Port (Port (SS#) of figure 1.4)	Output	Slave device select (SS#) output

#### 1.6 Software

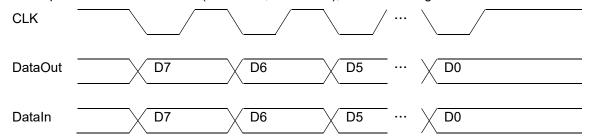
#### 1.6.1 Operation Overview

Utilizing the clock synchronous serial communication functionality of the microcontroller, clock synchronous single master control is implemented using the internal clock.

Refer to the User's Manual: Hardware of the microcontroller and the data sheet of the slave device to determine the usable serial clock frequencies.

### (4) Single-SPI Control

Control is performed in SPI mode 3 (CPOL = 1, CPHA = 1), as shown in figure 1.5.

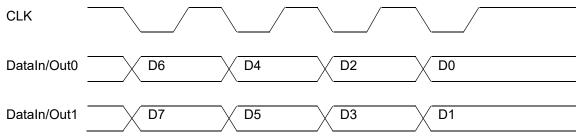


- MCU->Slave device transmission:Transmission of transmit data is started on the falling edge of the transfer clock.
  - Slave device ->MCU reception : The receive data is taken in on the rising edge of the transfer clock.
  - MSB-first mode transfer.
  - The level of the CLK pin is held high when no transfer processing is in progress.

Figure 1.5 Timing of Controllable Slave Devices for Single-SPI

#### (5) Dual-SPI Control

Control is performed in SPI mode 3 (CPOL = 1, CPHA = 1), as shown in figure 1.6.



- MCU->Slave device transmission:Transmission of transmit data is started on the falling edge of the transfer clock.
- · Slave device ->MCU reception : The receive data is taken in on the rising edge of the transfer clock.
- MSB-first mode transfer.
- The level of the CLK pin is held high when no transfer processing is in progress.

Figure 1.6 Timing of Controllable Slave Devices for Dual-SPI

# (6) Quad-SPI Control

Control is performed in SPI mode 3 (CPOL = 1, CPHA = 1), as shown in figure 1.7.

CLK

DataIn/Out0

D4

D5

D1

DataIn/Out2

D6

D2

DataIn/Out3

D7

D3

- MCU->Slave device transmission:Transmission of transmit data is started on the falling edge of the transfer clock.
- Slave device ->MCU reception : The receive data is taken in on the rising edge of the transfer clock.
- MSB-first mode transfer.
- The level of the CLK pin is held high when no transfer processing is in progress.

Figure 1.7 Timing of Controllable Slave Devices for Quad-SPI

#### 1.6.2 Serial Flash Memory Chip Select Pin Control

The chip select pin of the serial flash memory is connected to a port of the microcontroller and controlled by general port output from the microcontroller.

Control is performed in the software to wait during the chip select setup time of the serial flash memory, which is the time interval from the falling edge of the serial flash memory's chip select (microcontroller port (SS#)) signal to the falling edge of the serial flash memory's clock (microcontroller CLK) signal.

In like manner, control is performed in the software to wait during the chip select hold time of the serial flash memory, which is the time interval from the rising edge of the serial flash memory's clock (microcontroller CLK) signal to the rising edge of the serial flash memory's chip select (microcontroller port (SS#)) signal.

In this module the wait intervals for the chip select setup time and chip select hold time are each approximately 1  $\mu$ s.

#### 1.6.3 Software Structure

Figure 1.8 shows the software structure.

Use the control software to create software for controlling slave devices.

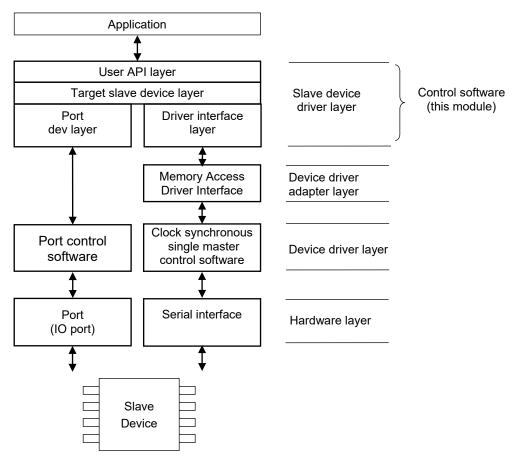


Figure 1.8 Software Structure

- (a) User API layer (r\_flash\_spi.c)
  - The user interface, this portion of the software is not dependent on lower-layer device drivers.
- (b) Target slave device layer (r flash spi type.c)
  - The serial flash memory control module, this portion of the software is not dependent on lower-layer device drivers.
- (c) Driver interface (I/F) layer (r flash spi drvif.c)
  - The common module for connecting to lower-layer device drivers.
  - A separate driver interface function is required to match the clock synchronous single master control module for each microcontroller model.
- (d) Port dev layer (r flash spi dev port.c)
  - The control module for controlling the slave device select signal (SS#) with a microcontroller port. The GPIO FIT module and MPC FIT module can be used.
- (e) Application
  - Sample code for controlling MX25L, MX66L, or MX25R family serial NOR flash memory, manufactured by Macronix International Co., Ltd., is provided for reference.
  - Sample code for controlling AT25QF family serial NOR flash memory, manufactured by Dialog Semiconductor Plc., is provided for reference.

# 1.6.4 Relationship Between Control Software and Clock Synchronous Single Master Control Software

The method whereby the control software and the clock synchronous single master control software are combined is described below.

Control of up to two slave devices, using up to two clock synchronous single master control modules, is supported. Register the clock synchronous single master control module (or modules) used as the driver interface function (or functions).

As shown below, it is possible to specify a separate driver for each device. For each device number, create processing code using the device driver API in the driver interface function that constitutes the driver interface layer.

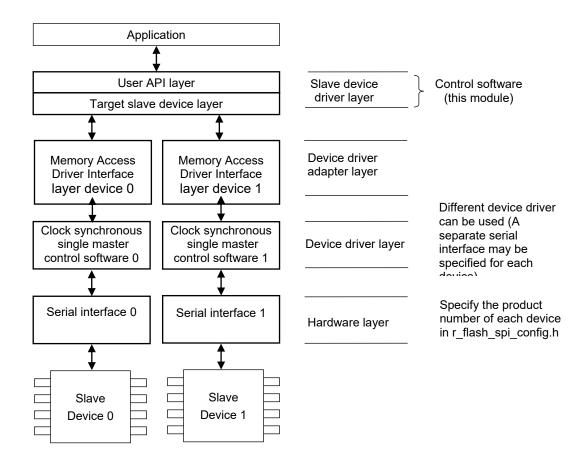


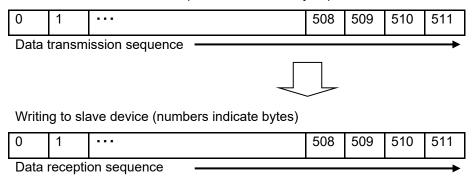
Figure 1.9 Software Configuration with Clock Synchronous Single Master Control Modules

#### 1.6.5 Data Buffers and Transmit/Receive Data

The control software is a block type device driver that sets transmit and receive data pointers as arguments. The arrangement of data in the data buffer in RAM and the transmit and receive sequences are illustrated below. Regardless of the endian mode and the serial communication function, data is transmitted in the order in which it is arranged in the transmit data buffer, and it is written to the receive data buffer in the order in which it is received.

#### Master transmit

Transmit data buffer in RAM (numbers indicate bytes)



#### Master receive

Reading from slave device (numbers indicate bytes)

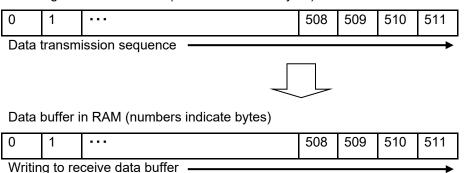


Figure 1.10 Data Buffers and Transmit/Receive Data

# 1.6.6 State Transition Diagram

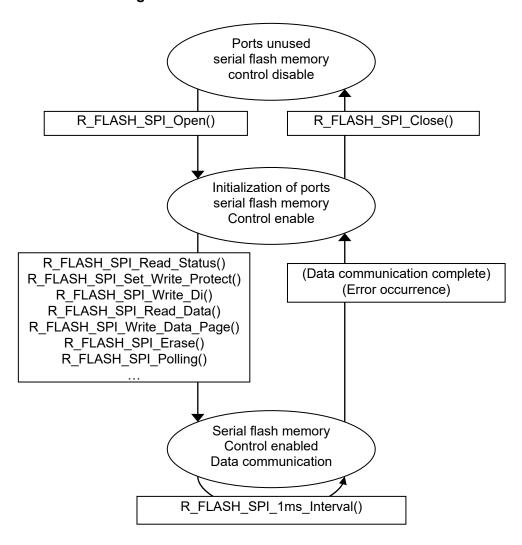


Figure 1.11 State Transition Diagram

#### 2. API Information

The names of the APIs of the control software follow the Renesas API naming standard.

# 2.1 Hardware Requirements

The microcontroller used must support the following functionality. Note that separate clock synchronous single master control software is required.

• I/O port

# 2.2 Software Requirements

When used with FIT support enabled, the control software is dependent on the following packages.

- r\_bsp Rev.5.00 or higher
- r\_memdrv\_rx Rev.1.04 or higher
- r rspi rx (when using the RSPI FIT module)
- r\_qspix\_rx (when using the QSPIX FIT module)
- r rsci rx (when using the RSCI FIT module)
- r qspi smstr rx (when using the QSPI FIT module for clock synchronous single master control)
- r scifa smstr rx (when using the SCIFA FIT module for clock synchronous single master control)
- r\_dmaca\_rx (only when using the DMACA FIT module for DMAC transfers)
- r\_dtc\_rx (only when using the DTC FIT module for DTC transfers)
- r\_cmt\_rx (only when using DMAC transfer or DTC transfer and the compare match timer (CMT) FIT module) Another timer or a software timer can be used instead.
- r\_gpio\_rx (only when using the GPIO and MPC FIT modules to control the GPIO)
- r mpc rx (only when using the GPIO and MPC FIT modules to control the MPC)

### 2.3 Supported Toolchain

The operation of the control software has been confirmed with the toolchain listed in 5.1, Confirmed Operation Environment.

# 2.4 Header Files

All the API calls and interface definitions used are listed in r\_flash\_spi\_if.h.

Configuration options for individual builds are selected in r\_flash\_spi\_config.h. The included statements should be in the following order.

```
#include "r_flash_spi_if.h"
#include "r flash spi config.h"
```

### 2.5 Integer Types

This project uses ANSI C99. These types are defined in stdint.h.



# 2.6 Compile Settings

The configuration option settings for the control software are specified in r\_flash\_spi\_config.h.

The option names and setting values are described below.

Configuration opti	ons in r_flash_spi_config.h	
#define FLASH_SPI_CFG_WEL_CHK Note: The default value is "1 (enabled)".	Selects whether or not the WEL bit is checked after the WREN command is issued. (1: enabled, 0: disabled)	
#define FLASH_SPI_CFG_LONGQ_ENABLE Note: The default value is "0 (disabled)".	Selects whether or not error log acquisition processing is performed for debugging, when using the BSP environment of a FIT module. (1: enabled, 0: disabled) When this option is set to "disabled", code for the relevant processing is omitted. When this option is set to "enabled", code for the relevant processing is included. To use this functionality, the LONGQ FIT module is also required. In addition, enable #define xxx_LONGQ_ENABLE in the clock synchronous single master control software of the specified	
#define FLASH_SPI_CFG_USE_GPIO_MPC_FIT	device.  Selects whether the GPIO FIT module or MPC FIT module is	
Note: The default value is "0 (disabled)".	used to control the SS# pin. (1: enabled, 0: disabled) When this option is set to "disabled", neither the GPIO FIT module nor the MPC FIT module controls the SS# pin. When this option is set to "enabled", the GPIO FIT module or MPC FIT module controls the SS# pin. To use this functionality, the GPIO FIT module or MPC FIT module is also required.	
#define FLASH_SPI_CFG_DEVx_INCLUDED  Note: The default value for device 0 is "1 (enabled)".  The "x" in DEVx represents the device number (x = 0 or 1).	This definition is related to device x. (1: enabled, 0: disabled) This option must be set to "enabled" for at least one device.	
#define FLASH_SPI_CFG_DEVx_MX25L #define FLASH_SPI_CFG_DEVx_MX66L #define FLASH_SPI_CFG_DEVx_MX25R #define FLASH_SPI_CFG_DEVx_AT25QF Note: The default values for device 0 are FLASH_SPI_CFG_DEVx_MX25L: 1, other: 0. The "x" in DEVx represents the device number (x = 0 or 1).	Select only one serial flash memory device to be controlled for device x (1: control target, 0: not control target).	

Configuration options in r_flash_spi_config.h				
#define FLASH_SPI_CFG_DEVx_SIZE_512K #define FLASH_SPI_CFG_DEVx_SIZE_2M #define FLASH_SPI_CFG_DEVx_SIZE_4M #define FLASH_SPI_CFG_DEVx_SIZE_4M #define FLASH_SPI_CFG_DEVx_SIZE_8M #define FLASH_SPI_CFG_DEVx_SIZE_16M #define FLASH_SPI_CFG_DEVx_SIZE_32M #define FLASH_SPI_CFG_DEVx_SIZE_64M #define FLASH_SPI_CFG_DEVx_SIZE_128M #define FLASH_SPI_CFG_DEVx_SIZE_256M #define FLASH_SPI_CFG_DEVx_SIZE_512M #define FLASH_SPI_CFG_DEVx_SIZE_1G Note: The default values for device 0 are FLASH_SPI_CFG_DEVx_SIZE_64M: 1, other: 0. The "x" in DEVx represents the device number (x = 0 or 1).	Select only one serial flash memory capacity to be controlled for device x (1: control target, 0: not control target).			
#define FLASH_SPI_CS_DEVx_CFG_PORTNO Note: The default value for device 0 is "'X'". The "x" in DEVx represents the device number (x = 0 or 1).	Specifies the port number assigned to SS# for device x. Enclose the setting value in single quotation marks (''). Configure Device x Port Number with 0 - 9, A - X.			
#define FLASH_SPI_CS_DEVx_CFG_BITNO Note: The default value for device 0 is "'0". The "x" in DEVx represents the device number (x = 0 or 1).	Specifies the bit number assigned to SS# for device x. Enclose the setting value in single quotation marks (' '). Configure Device x Bit Number with 0 – 7.			

# 2.7 Arguments

The structure for the arguments of the API functions is shown below. This structure is listed in r\_flash\_spi\_if.h, along with the prototype declarations of the API functions.

```
/* FLASH Memory information */
typedef struct
 /* Temporary counter or Number of bytes to be written in a page
  using write/read data in a Security register page */
                      /* 20 bytes
} flash spi info t;
/* FLASH Memory size information */
typedef struct
*/
                                                      */
                                                      */
/* FLASH Memory erase information */
typedef struct
 */
                                                      */
} flash_spi_erase_info_t;
                                                      */
/* FLASH Memory register information */
typedef struct
 uint8_t status;  /* Status register */
uint8_t config1;  /* Configuration or Configuration-1 register */
uint8_t config2;  /* Configuration-2 register */
uint8_t rsv[1];
*/
```

### 2.8 Code Size

The sizes of ROM, RAM and maximum stack usage associated with this module are listed below.

The ROM (code and constants) and RAM (global data) sizes are determined by the build-time configuration options described in 2.6, Compile Settings.

The values in the table below are confirmed under the following conditions.

Module Revision: r\_flash\_spi rev.3.20

Compiler Version: Renesas Electronics C/C++ Compiler Package for RX Family V3.04.00

(The option of "-lang = c99" is added to the default settings of the integrated development environment.)

GCC for Renesas RX 8.3.0.202202

(The option of "-std = gnu99" is added to the default settings of the integrated

development environment.)

IAR C/C++ Compiler for Renesas RX version 4.20.3

(The default settings of the integrated development environment.)

Configuration Options: Default settings

Operating frequency: RX113 ICLK: 32 MHz, PCLKB: 32 MHz

RX231 ICLK: 54 MHz, PCLKB: 27 MHz

RX64M ICLK: 120MHz, PCLKA: 120MHz, PCLKB: 60MHz RX71M ICLK: 240MHz, PCLKA: 120MHz, PCLKB: 60MHz

Operating voltage: 3.3V Endian: Little endian

The clock synchronous single master control software: RSPI

Data transfer mode: Software

Confirmation conditions: r\_flash\_spi.c, r\_flash\_spi\_dev\_port\_iodefine.c, r\_flash\_spi\_drvif.c,

r\_flash\_spi\_type.c, r\_flash\_spi\_type\_sub.c

	ROM, RAM and Stack Code Sizes				
Device	Category	Memory Used			
		Renesas Compiler	GCC	IAR Compiler	
RX113	ROM	4,491 bytes	11,396 bytes	7,825 bytes	
	RAM	8 bytes	8 bytes	8 bytes	
	STACK	140 bytes	-	200 bytes	
RX231	ROM	4,495 bytes	11,436 bytes	7,860 bytes	
	RAM	8 bytes	8 bytes	8 bytes	
	STACK	140 bytes	-	200 bytes	

	ROM, RAM and Stack Code Sizes				
Device	Category	Memory Used			
		Renesas Compiler	GCC	IAR Compiler	
RX64M	ROM	4,535 bytes	11,436 bytes	7,902 bytes	
	RAM	8 bytes	8 bytes	8 bytes	
	STACK	140 bytes	-	232 bytes	
RX71M	ROM	4,535 bytes	11,436 bytes	7,823 bytes	
	RAM	8 bytes	8 bytes	8 bytes	
	STACK	140 bytes	-	232 bytes	

### 2.9 Return Values

The API function return values are shown below. This enumerated type is listed in r\_flash\_spi\_if.h, along with the prototype declarations of the API functions.

# 2.10 Adding the Driver to Your Project

This module must be added to each project in which it is used. Renesas recommends the method using the Smart Configurator described in (1) or (2) or (4) below. However, the Smart Configurator only supports some RX devices. Please use the methods of (3) for RX devices that are not supported by the Smart Configurator.

- (1) Adding the FIT module to your project using the Smart Configurator in e<sup>2</sup> studio
  By using the Smart Configurator in e<sup>2</sup> studio, the FIT module is automatically added to your project.
  Refer to "RX Smart Configurator User's Guide: e<sup>2</sup> studio (R20AN0451)" for details.
- (2) Adding the FIT module to your project using the Smart Configurator in CS+ By using the Smart Configurator Standalone version in CS+, the FIT module is automatically added to your project. Refer to "RX Smart Configurator User's Guide: CS+ (R20AN0470)" for details.
- (3) Adding the FIT module to your project in CS+ In CS+, please manually add the FIT module to your project. Refer to "RX Family Adding Firmware Integration Technology Modules to CS+ Projects (R01AN1826)" for details.
- (4) Adding the FIT module to your project using the Smart Configurator in IAREW By using the Smart Configurator Standalone version, the FIT module is automatically added to your project. Refer to "RX Smart Configurator User's Guide: IAREW (R20AN0535)" for details.

# 2.11 Using the Serial Flash Memory Control Software in Other Than an FIT Module Environment

To use the serial flash memory control software in an environment in which FIT modules such as r\_bsp are not used, perform the following.

Comment out the line #include "platform.h" in #r flash spi if.h.

Include the following header files in #r\_flash\_spi\_if.h.

```
#include "iodefine.h"
#include <stdint.h>
#include <stdbool.h>
#include <stddef.h>
#include <machine.h>
```

Disable the option #define FLASH\_SPI\_CFG\_USE\_FIT in #r\_flash\_spi\_if.h.

Add the definition #define FLASH\_SPI\_CFG\_xxx (replacing xxx with the microcontroller name using all capital letters) to #r\_flash\_spi\_if.h. For example, for the RX64M microcontroller use the string FLASH\_SPI\_CFG\_RX64M.

In # r\_flash\_spi\_if.h add the enum definitions shown below. Also add the #define definitions shown below. Set the system clock (ICLK) value in BSP\_ICLK\_HZ. Note that it is possible that some of these definitions may duplicate other FIT module definitions. Insert the lines #ifndef SMSTR\_WAIT and #define SMSTR\_WAIT at the beginning of the definitions and insert #endif as the last line.

```
#ifndef SMSTR_WAIT
#define SMSTR_WAIT
typedef enum
{
    BSP_DELAY_MICROSECS = 1000000,
    BSP_DELAY_MILLISECS = 1000,
    BSP_DELAY_SECS = 1
} bsp_delay_units_t;

#define BSP_ICLK_HZ (120000000) /* ICLK = 120MHz */
#endif /* #ifndef SMSTR WAIT */
```

### 2.12 Pin States

Table 2.1 lists the pin states after a power on reset and after execution of various API functions.

As shown in 1.5.1 (1), Single-SPI Control, this module supports SPI mode 3 (CPOL = 1, CPHA = 1). Regardless of the hardware configuration, after a power on reset, control the GPIO from the user side and put the select pin into the high-output state to use this mode.

Also, the slave device select pin is in the GPIO high-output state after R\_FLASH\_SPI\_Close() runs. Review the pin settings if necessary.

Table 2.1 Pin States after Function Execution

Function Name	Slave Device Select Pin*
(After power on reset)	GPIO input state
Before R_FLASH_SPI_Open()	GPIO high-output state
	Set on user side
After R_FLASH_SPI_Open()	GPIO high-output state
	Set by this module
After R_FLASH_SPI_Close()	GPIO high-output state
	Set by this module

Note: \* Use an external resistor to pull up the slave device select pin. See 1.5.1, Hardware Configuration Example.

# 2.13 "for", "while" and "do while" statements

In this module, "for", "while" and "do while" statements (loop processing) are used in processing to wait for register to be reflected and so on. For these loop processing, comments with "WAIT\_LOOP" as a keyword are described. Therefore, if user incorporates fail-safe processing into loop processing, user can search the corresponding processing with "WAIT\_LOOP".

The following shows example of description.

```
while statement example :
/* WAIT LOOP */
while(0 == SYSTEM.OSCOVFSR.BIT.PLOVF)
{
    /* The delay period needed is to make sure that the PLL has stabilized. */
}

for statement example :
/* Initialize reference counters to 0. */
/* WAIT LOOP */
for (i = 0; i < BSP REG PROTECT TOTAL ITEMS; i++)
{
    g protect counters[i] = 0;
}

do while statement example :
/* Reset completion waiting */
do
{
    reg = phy read(ether channel, PHY REG CONTROL);
    count++;
} while ((reg & PHY_CONTROL_RESET) && (count < ETHER_CFG_PHY_DELAY_RESET)); /* WAIT_LOOP */</pre>
```

#### 3. API Functions

# R\_FLASH\_SPI\_Open()

This function is run first when using the APIs of the serial flash memory control software.

#### **Format**

#### **Return Values**

```
FLASH_SPI_SUCCESS /* Successful operation */
FLASH_SPI_ERR_PARAM /* Parameter error */
```

# **Properties**

Prototype declarations are contained in r\_flash\_spi\_if.h.

# **Description**

Initializes the slave device select pin of the device number specified by the argument devno. After initialization the pin is in the general output port high-output state.

Do not call this function when communication is in progress. Communication cannot be guaranteed if the function is called when communication is in progress.

#### Example

```
flash_spi_status_t ret = FLASH_SPI_SUCCESS;
ret = R FLASH SPI Open(FLASH SPI DEV0);
```

# **Special Notes**

After calling this user API function, it is recommended that R\_FLASH\_SPI\_Polling() be used to confirm that the serial flash memory write cycle has completed. The next read or write processing will not be accepted while the serial flash memory write cycle is in progress.

However, it is possible to access the serial flash memory during the write cycle by, for example, issuing a system reset while the serial flash memory write cycle is in progress and restarting serial flash memory control from the beginning.



# R\_FLASH\_SPI\_Close()

This function is used to close the serial flash memory control software when it is in use.

### **Format**

```
flash_spi_status_t R_FLASH_SPI_Close(
    uint8_t devno
)
```

#### **Parameters**

devno

Device number (0, 1)

#### **Return Values**

```
FLASH_SPI_SUCCESS /* Successful operation */
FLASH_SPI_ERR_PARAM /* Parameter error */
FLASH_SPI_ERR_OTHER /* Other error */
```

# **Properties**

Prototype declarations are contained in r\_flash\_spi\_if.h.

#### **Description**

Sets the slave device select pin of the device number specified by the argument devno to function as a general I/O port. After the function runs, the pin is in the general output port high-output state. Do not call this function when communication is in progress. Communication cannot be guaranteed if the function is called when communication is in progress.

#### **Example**

```
flash_spi_status_t ret = FLASH_SPI_SUCCESS;
ret = R_FLASH_SPI_Close(FLASH_SPI_DEV0);
```

# **Special Notes**

The state of the slave device select pin after this function is called is different from its state after a reset (general input port state). Review the pin settings if necessary.

Before calling this user API function, it is recommended that R\_FLASH\_SPI\_Polling() be used to confirm that the serial flash memory write cycle has completed. This makes it possible to restart serial flash memory control because the serial flash memory has not transitioned to the write cycle.



# R\_FLASH\_SPI\_Read\_Status()

This function is used to read the status register.

#### **Format**

```
flash_spi_status_t R_FLASH_SPI_Read_Status(
    uint8_t devno,
    uint8_t * p_status
)
Parameters
devno
```

Status register storage buffer (size: 1 byte)

# Return Values

\* p\_status

Device number (0, 1)

```
FLASH_SPI_SUCCESS /* Successful operation */
FLASH_SPI_ERR_PARAM /* Parameter error */
FLASH_SPI_ERR_HARD /* Hardware error */
FLASH_SPI_ERR_OTHER /* Other task has acquired clock synchronous single master control software resources, or other error */
```

#### **Properties**

Prototype declarations are contained in r\_flash\_spi\_if.h.

#### Description

Reads the status register and stores the contents in p\_status. The following information is stored in p\_status: Refer to the data sheet for information on protected areas and protected bits.

<MX25L, MX66L, or MX25R family serial NOR flash memory of Macronix International Co., Ltd.>

Table 3.1 MX25L, MX66L, or MX25R family serial NOR flash memory

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
SRWD	QE	BP3	BP2	BP1	BP0	WEL	WIP
(status	(quad	(level of	(level of	(level of	(level of	(write	(write in
register write	enable)	protected	protected	protected	protected	enable	progress
protect)		block)	block)	block)	block)	latch)	bit)
1 = status	1 = quad	*1	*1	*1	*1	1 = write	1 = write
register write	enable					enable	operation
disable	0 = not quad					0 = not write	0 = not in
	enable					enable	write
							operation
Non-volatile	Non-volatile	Non-volatile	Non-volatile	Non-volatile	Non-volatile	Volatile bit	Volatile bit
bit	bit	bit	bit	bit	bit		

Note 1: Set to 1, a designated memory area is protected from PROGRAM and ERASE operations.

<AT25QF family serial NOR flash memory of Dialog Semiconductor Plc.>

Table 3.2 AT25QF family serial NOR flash memory

Bit	Mnemonic	Name	Type		Description	
7	SRP0	Status Register Protection bit 0	R/W		*4	
6	SEC	Block Protection	R/W	*3	*4	
5	ТВ	Top or Bottom Protection	R/W	*2	*4	
4	BP2	Block Protection bit 2	R/W	*1	*4	
3	BP1	Block Protection bit 1	R/W	*1	*4	
2	BP1	Block Protection bit 0	R/W	*1	*4	
1 WEL	\A/E1	Write Enable Latch Status	R	0	Device is not Write Enable (default).	
	VVEL			1	Device is Write Enable.	
	RDY /BSY	Ready/Busy Status	R	0	Device is ready.	
0				1	Device is busy with an internal operation.	

Note 1: Set to 0 or 1, determine how much of the array is protected.

Note 2: Set to 0 or 1, selects between top of the array or bottom of the array protection.

Note 3: Set to 0 or 1, selects between large and small block size protection.

Note 4: See the specification of Flash memory.

#### **Example**

```
flash_spi_status_t ret = FLASH_SPI_SUCCESS;
uint32_t stat = 0;

ret = R_FLASH_SPI_Read_Status(FLASH_SPI_DEV0, &stat);
```

# **Special Notes**

The clock synchronous single master control software resources are acquired at the start of the processing, and the resources are released and the end of the processing.



# R\_FLASH\_SPI\_Read\_Status2()

This function is used to read the status register 2. It is a dedicated API function for AT25QF family serial NOR flash memory of Dialog Semiconductor Plc.

```
flash_spi_status_t R_FLASH_SPI_Read_Status2(
    uint8 t devno,
    uint8_t * p_status
)
Parameters
devno
   Device number (0, 1)
```

Status register storage buffer (size: 1 byte)

\* p\_status

```
Return Values
FLASH_SPI_SUCCESS
                               /* Successful operation */
FLASH_SPI_ERR_PARAM
                               /* Parameter error */
FLASH_SPI_ERR_HARD
                               /* Hardware error */
FLASH_SPI_ERR_OTHER
                               /* Other task has acquired clock synchronous single
                                  master control software resources, or other error */
```

#### **Properties**

Prototype declarations are contained in r\_flash\_spi\_if.h.

#### **Description**

Reads the status register 2 and stores the contents in p\_status. The following information is stored in p\_status:

# <AT25QF family serial NOR flash memory of Dialog Semiconductor Plc.>

Table 3.3 AT25QF family serial NOR flash memory

Bit	Mnemonic	Name	Type	Description	
7	7 E_SUS	Erase Suspend Status	R	0	Erase operation is not suspended (default).
'				1	Erase operation is suspended.
6	CMP	Complement Block Protection	R/W	*1	*2
		Lock Security Register 3	R/W	0	Security Register page-3 is not locked (default).
5	5 LB3			1	Security Register page-3 cannot be erased/programmed. *3
			R/W	0	Security Register page-2 is not locked (default).
4	4 LB2	Lock Security Register 2		1	Security Register page-2 cannot be erased/programmed. *3
	3 BP1	Lock Security Register 1	R/W	0	Security Register page-1 is not locked (default).
3				1	Security Register page-1 cannot be erased/programmed. *3
2	2 P_SUS	Program Suspend Status	R/	0	Program operation is not suspended (default).
-				1	Program operation is suspended.
1	1 QE	Quad Enable	R/W	0	HOLD and WP function normally.
	QΕ			1	HOLD and WP are I/O pins (default).
0	SRP1	Status Register Protect bit 1	R/W		*2

Note 1: Set to 0 or 1, complements the effect of the other bits.

Note 2: See the specification of Flash memory.

Note 3: Once a Lock Bit is set to 1, the corresponding Security Register is permanently locked. The Erase Security Register Page instruction is ignored for Security Registers with their Lock Bit set.

#### **Example**

```
flash_spi_status_t ret = FLASH_SPI_SUCCESS;
uint32_t stat = 0;

ret = R_FLASH_SPI_Read_Status2(FLASH_SPI_DEV0, &stat);
```

#### **Special Notes**

The clock synchronous single master control software resources are acquired at the start of the processing, and the resources are released and the end of the processing.

# R\_FLASH\_SPI\_Read\_Status3()

This function is used to read the status register 3. It is a dedicated API function for AT25QF family serial NOR flash memory of Dialog Semiconductor Plc.

#### **Format**

```
flash_spi_status_t R_FLASH_SPI_Read_Status3(
    uint8_t devno,
    uint8_t * p_status
)
```

#### **Parameters**

devno

Device number (0, 1)

\* p\_status

Status register storage buffer (size: 1 byte)

#### **Return Values**

```
FLASH_SPI_SUCCESS /* Successful operation */
FLASH_SPI_ERR_PARAM /* Parameter error */
FLASH_SPI_ERR_HARD /* Hardware error */
FLASH_SPI_ERR_OTHER /* Other task has acquired clock synchronous single master control software resources, or other error */
```

#### **Properties**

Prototype declarations are contained in r\_flash\_spi\_if.h.

#### Description

Reads the status register 3 and stores the contents in p\_status. The following information is stored in p\_status:

<AT25QF family serial NOR flash memory of Dialog Semiconductor Plc.>

Table 3.4 AT25QF family serial NOR flash memory

Bit	Mnemonic	Name	Туре		Description
7	Res	Reserved	R	0	Reserved bit.
6:5	DRV[1:0]	Drive Strength	R/W	11	Drive level. Th DRV1 and DRV0 bits are used to determine the output drive strength during read operations. One of the setting of below allows the drive strength to be set by hardware based on the VCC level. Four drive settings are supported.  This field is encoded as follows:  11: Auto (7pF base on VCC level. 10: 50% (15pF). 01: 75% (22pF). 00: 100% (30pF).
4:0	Res	Reserved	R	0	Reserved bit.

### **Example**

```
flash_spi_status_t ret = FLASH_SPI_SUCCESS;
uint32_t stat = 0;

ret = R FLASH SPI Read Status3(FLASH SPI DEV0, &stat);
```

# **Special Notes**

The clock synchronous single master control software resources are acquired at the start of the processing, and the resources are released and the end of the processing.

# R\_FLASH\_SPI\_Set\_Write\_Protect()

This function is used to make write protect settings.

#### **Format**

```
flash_spi_status_t R_FLASH_SPI_Set_Write_Protect(
    uint8_t devno,
    uint8_t wpsts
)
```

#### **Parameters**

devno

Device number (0, 1)

wpsts

Write protect setting data

#### **Return Values**

```
FLASH_SPI_SUCCESS /* Successful operation */
FLASH_SPI_ERR_PARAM /* Parameter error */
FLASH_SPI_ERR_HARD /* Hardware error */
FLASH_SPI_ERR_OTHER /* Other task has acquired clock synchronous single master control software resources, or other error */
```

#### **Properties**

Prototype declarations are contained in r\_flash\_spi\_if.h.

#### **Description**

Make write protect settings. SRWD is cleared to 0.

Specify the write protect setting data (wpsts) as indicated below.

Refer to the data sheet for information on protected areas and protected bits.

• <MX25L, MX66L, or MX25R family serial NOR flash memory of Macronix International Co., Ltd> Make top and bottom settings during configuration write processing.

wpsts	BP3	BP2	BP1	BP0
0x00	0	0	0	0
0x01	0	0	0	1
0x02	0	0	1	0
0x03	0	0	1	1
0x04	0	1	0	0
0x05	0	1	0	1
0x06	0	1	1	0
0x07	0	1	1	1
0x08	1	0	0	0
0x09	1	0	0	1
0x0a	1	0	1	0
0x0b	1	0	1	1
0x0c	1	1	0	0
0x0d	1	1	0	1
0x0e	1	1	1	0
0x0f	1	1	1	1

# <AT25QF family serial NOR flash memory of Dialog Semiconductor Plc>

Make large and small block size, top, and bottom settings during status register 1 write processing.

Make compliment settings during status register 2 write processing.

wpsts	BP2	BP1	BP0
0x00	0	0	0
0x01	0	0	1
0x02	0	1	0
0x03	0	1	1
0x04	1	0	0
0x05	1	0	1
0x06	1	1	0
0x07	1	1	1

When this user API function completes successfully, the serial flash memory transitions to a write cycle. Do not fail to confirm write completion with R\_FLASH\_SPI\_Polling(). If the next read or write processing starts when a previous write cycle is in progress, the serial flash memory will not accept the new processing. R\_FLASH\_SPI\_Polling() can be called at any time specified by the user. This allows a user application to perform other processing while a write cycle is in progress. See figure 3.1 for details.

```
#define FLASH_WR_BUSY_WAIT (uint32_t)(40)
                                         /* 40 * 1ms = 40ms */
flash spi status t ret = FLASH SPI SUCCESS;
uint32 t
                     loop cnt = 0;
flash spi poll mode t mode;
ret = R FLASH SPI Set Write Protect(FLASH SPI DEV0, 0);
if (FLASH SPI SUCCESS > ret)
{
  /* Error */
}
loop cnt = FLASH WR BUSY WAIT;
mode = FLASH SPI MODE REG WRITE POLL;
   /* FLASH is busy.
     User application can perform other processing while flash is busy. */
  ret = R FLASH SPI Polling(FLASH SPI DEV0, mode);
  if (FLASH SPI SUCCESS BUSY != ret)
     /* FLASH is ready or error. */
     break;
  loop cnt--;
  while (0 != loop cnt);
if ((0 == loop cnt) || (FLASH SPI SUCCESS > ret))
  /* Error */
}
```

## **Special Notes**

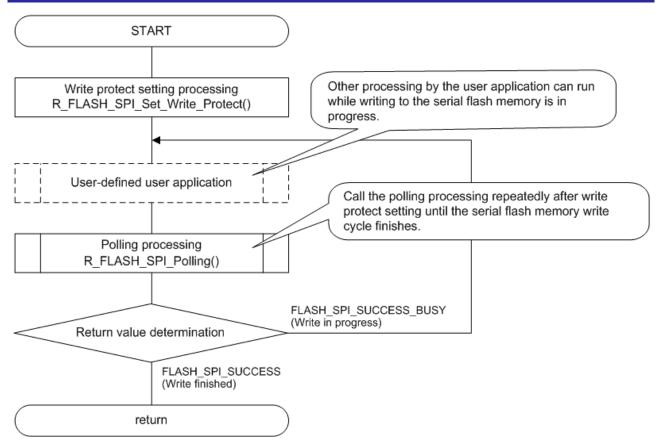


Figure 3.1 R\_FLASH\_SPI\_Set\_Write\_Protect() Processing Example

# R\_FLASH\_SPI\_Write\_Di()

This function is used to disable write operation.

## **Format**

```
flash_spi_status_t R_FLASH_SPI_Write_Di(
    uint8_t devno
)
```

## **Parameters**

devno

Device number (0, 1)

# **Return Values**

```
FLASH_SPI_SUCCESS /* Successful operation */
FLASH_SPI_ERR_PARAM /* Parameter error */
FLASH_SPI_ERR_HARD /* Hardware error */
FLASH_SPI_ERR_OTHER /* Other task has acquired clock synchronous single master control software resources, or other error */
```

## **Properties**

Prototype declarations are contained in r\_flash\_spi\_if.h.

## **Description**

Transmits the WRDI command and clears the WEL bit in the status register.

# **Example**

```
flash_spi_status_t ret = FLASH_SPI_SUCCESS;
ret = R_FLASH_SPI_Write_Di(FLASH_SPI_DEVO);
```

## **Special Notes**

# R\_FLASH\_SPI\_Read\_Data()

This function is used to read data from the serial flash memory.

```
Format
```

```
flash_spi_status_t R_FLASH_SPI_Read_Data(
    uint8_t devno,
    flash_spi_info_t * p_flash_spi_info
)
```

## **Parameters**

devno

Device number (0, 1)

\* p\_flash\_spi\_info

Serial flash memory information structure. Use a structure address aligned with a 4-byte boundary.

Specify the start address of the memory read.

cnt

Specify the read byte count. The allowable setting range is 1 to 4,294,967,295. A setting of 0 causes an error to be returned.

data cnt

Read byte count (Used by the control software, so setting by the user is prohibited.)

\*p\_data

Specify the address of the read data storage buffer. Use a buffer address aligned with a 4-byte boundary.

op\_mode

SPI mode setting.

Please select one from the following:

```
FLASH_SPI_SINGLE /* Single-SPI (full-duplex communication) */
FLASH_SPI_DUAL /* Dual-SPI (half-duplex communication) */
FLASH_SPI_QUAD /* Quad-SPI (half-duplex communication) */
```

## **Return Values**

```
FLASH_SPI_SUCCESS /* Successful operation */
FLASH_SPI_ERR_PARAM /* Parameter error */
FLASH_SPI_ERR_HARD /* Hardware error */
FLASH_SPI_ERR_OTHER /* Other task has acquired clock synchronous single master control software resources. or other error */
```

# **Properties**

Prototype declarations are contained in r flash spi if.h.

# **Description**

Reads the specified number of bytes of data from the specified address in the serial flash memory and stores the data in p\_data.

The maximum read address is the serial flash memory capacity – 1.

Rollover read operations are not supported. After the end address is read, processing ends. It is then necessary to reset the address and call this API function again.

FLASH\_SPI\_ERR\_PARAM is returned if the total value of the read byte count, cnt, and specified address, addr. exceeds the maximum read address.

DMAC transfer or DTC transfer occurs when the transfer size conditions of the clock synchronous single master control software are matched. Otherwise, operation switches to software transfer.

## **Special Notes**

To speed up data transfers, align the start address with a 4-byte boundary when specifying data storage buffer pointers.

The clock synchronous single master control software resources are acquired at the start of the processing, and the resources are released and the end of the processing.

When reading data in QSPIX memory-mapped mode, data can only be read from addresses in a specified bank. A bank is a 64MB sliding access window into the QSPI device flash memory space. The code is not designed to read data from flash memory across banks. If the requested amount of data is read consecutively from the address area of two consecutive bank areas, this function will return the error "FLASH\_SPI\_ERR\_OTHER".

# R\_FLASH\_SPI\_Write\_Data\_Page()

This function is used to write data to the serial flash memory in single-page units.

```
Format
```

```
flash_spi_status_t R_FLASH_SPI_Write_Data_Page(
    uint8_t devno,
    flash_spi_info_t * p_flash_spi_info
)
```

### **Parameters**

devno

Device number (0, 1)

\* p\_flash\_spi\_info

Serial flash memory information structure. Use a structure address aligned with a 4-byte boundary.

Specify the start address of the memory write.

cnt

Specify the write byte count. The allowable setting range is 1 to 4,294,967,295. A setting of 0 causes an error to be returned.

data cnt

Write byte count (Used by the control software, so setting by the user is prohibited.)

\*p data

Specify the address of the write data storage buffer.

op mode

SPI mode setting.

Please select one from the following:

FLASH\_SPI\_SINGLE /\* Single-SPI (full-duplex communication) \*/
FLASH\_SPI\_QUAD /\* Quad-SPI (half-duplex communication) \*/
%: Setting of FLASH\_SPI\_DUAL is prohibited.

## **Return Values**

```
FLASH_SPI_SUCCESS /* Successful operation */
FLASH_SPI_ERR_PARAM /* Parameter error */
FLASH_SPI_ERR_HARD /* Hardware error */
FLASH_SPI_ERR_OTHER /* Other task has acquired clock synchronous single master control software resources, or other error */
```

## **Properties**

Prototype declarations are contained in r flash spi if.h.

## **Description**

Writes the specified number of bytes of data (up to a maximum size of 1 page) in p\_data to the serial flash memory, starting from the specified address.

When writing a large volume of data, communication is divided into page units. This prevents a situation in which other processing is not possible while communication is in progress.

Writing to the serial flash memory is only possible when write protect has been canceled.

It is not possible to write to a protected page. Attempting to do so returns the error FLASH\_SPI\_ERR\_WP. The maximum write address is the serial flash memory capacity – 1.

The maximum write byte count (cnt) setting value is the capacity of the serial flash memory.

FLASH\_SPI\_ERR\_PARAM is returned if the total value of the write byte count, cnt, and specified address, addr, exceeds the maximum write address.

DMAC transfer or DTC transfer occurs when the transfer size conditions of the clock synchronous single master control software are matched. Otherwise, operation switches to software transfer.

When a byte count exceeding 1 page is specified, the remaining byte count and next address information remain in the serial flash memory information stricture (p\_flash\_info) after processing of a single page write



finishes. It is possible to write the remaining bytes by specifying p\_flash\_info unmodified in this API function again.

After this user API function finishes successfully, the serial flash memory transitions to the write cycle. Do not fail to confirm that the write has finished with R\_FLASH\_SPI\_Polling(). If an attempt is made to perform the next read or write processing while a write cycle is in progress, the serial flash memory will not accept that processing.

R\_FLASH\_SPI\_Polling() can be called at any time specified by the user. This makes it possible for the user application to perform other processing while a write cycle is in progress. See figure 3.2 for details.

## **Example**

```
#define FLASH PP BUSY WAIT (uint32 t)(3) /* 3 * 1ms = 3ms */
flash spi status t    ret = FLASH SPI SUCCESS;
flash_spi_info_t
                    Flash Info W;
                    buf1[128/sizeof(uint32 t)];
uint32 t
                             /* the buffer boundary (4-byte unit) */
uint32 t
                    loop cnt = 0;
Flash Info W.addr
                    = 0;
Flash Info W.cnt = 128;
Flash Info W.p data = (uint8 t *)&buf1[0];
Flash Info W.op mode = FLASH SPI QUAD;
do
{
  ret = R FLASH SPI Write Data Page(FLASH SPI DEV0, &Flash Info W);
  if (FLASH SPI SUCCESS > ret)
     /* Error */
  loop cnt = FLASH PP BUSY WAIT;
  mode = FLASH SPI MODE PROG POLL;
  do
   {
     /* FLASH is busy.
        User application can perform other processing while flash is busy. */
        ret = R FLASH SPI Polling(FLASH SPI DEV0, mode);
        if (FLASH SPI SUCCESS BUSY != ret)
           /* FLASH is ready or error. */
           break;
        loop cnt--;
        while (0 != loop cnt);
}
while (0 != Flash Info W.cnt);
if ((0 == loop cnt) || (FLASH SPI SUCCESS > ret))
{
   /* Error */
```

# **Special Notes**

To speed up data transfers, align the start address with a 4-byte boundary when specifying data storage buffer pointers.

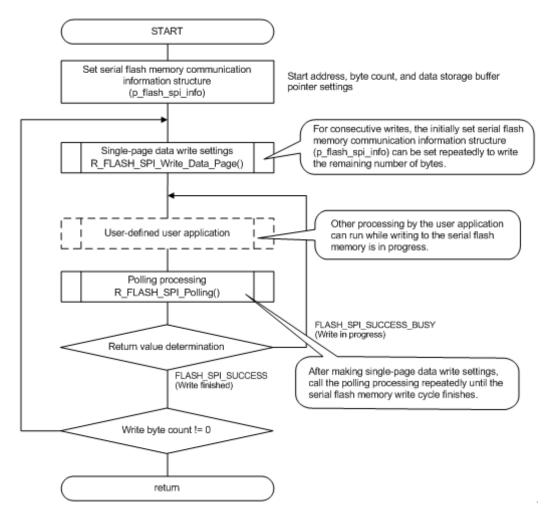


Figure 3.2 R\_FLASH\_SPI\_Write\_Data\_Page() Processing Example

# R FLASH SPI Erase()

Based on the mode setting, this function erases all the data in the specified sector (sector erase), all the data in the specified block (block erase: 32 KB block or 64 KB block), or all the data on the specified chip (chip erase).

### **Format**

```
flash_spi_status_t R_FLASH_SPI_Erase(
    uint8_t devno,
    flash_spi_erase_info_t * p_flash_spi_erase_info
)
```

### **Parameters**

devno

Device number (0, 1)

\* p\_flash\_spi\_erase\_info

Serial flash memory erase information structure. Use a structure address aligned with a 4-byte boundary.

Specify the start address of the memory write.

mode

Erase mode setting

Select one of the following:

• <MX25L, MX66L, or MX25R family serial NOR flash memory of Macronix International Co., Ltd.>

```
FLASH_SPI_MODE_C_ERASE /* Erases all the data on the chip (chip erase) */
FLASH_SPI_MODE_S_ERASE /* Erases all the data on the sector (sector erase) */
FLASH_SPI_MODE_B32K_ERASE /* Erases all the data in the block (block erase: 32 KB) */
FLASH_SPI_MODE_B64K_ERASE /* Erases all the data in the block (block erase: 64 KB) */
```

• <AT25QF family serial NOR flash memory of Dialog Semiconductor Plc.>

```
FLASH_SPI_MODE_C_ERASE /* Erases all the data on the chip (chip erase) */
FLASH_SPI_MODE_B4K_ERASE /* Erases all the data in the block (block erase: 4 KB) */
FLASH_SPI_MODE_B64K_ERASE /* Erases all the data in the block (block erase: 32 KB) */
FLASH_SPI_MODE_B64K_ERASE /* Erases all the data in the block (block erase: 64 KB) */
FLASH_SPI_MODE_SCUR_ERASE /* Erases the security register pages */
```

### **Return Values**

```
FLASH_SPI_SUCCESS /* Successful operation */
FLASH_SPI_ERR_PARAM /* Parameter error */
FLASH_SPI_ERR_HARD /* Hardware error */
FLASH_SPI_ERR_OTHER /* Other task has acquired clock synchronous single master control software resources, or other error */
```

## **Properties**

Prototype declarations are contained in r flash spi if.h.

## **Description**

For sector erase, specify the start address of the sector in addr.

For block erase, specify the start address of the block in addr.

For security erase, specify the start address of the security register pages in addr.

For chip erase, set addr to 0x00000000.

Erasing data in serial flash memory is only possible when write protect has been canceled.

It is not possible to erase data in a protected area. Attempting to do so returns the error FLASH SPI ERR OTHER.

When this user API function completes successfully, the serial flash memory transitions to an erase cycle. Do not fail to confirm erase completion with R\_FLASH\_SPI\_Polling(). If the next read or write processing starts when a previous erase cycle is in progress, the serial flash memory will not accept the new processing. R\_FLASH\_SPI\_Polling() can be called at any time specified by the user. This allows a user application to perform other processing while an erase cycle is in progress.



See figure 3-3 for details.

## Example

```
#define FLASH SE BUSY WAIT (uint32 t)(200) /* 200 * 1ms = 200ms */
flash spi status t
                      ret = FLASH SPI SUCCESS;
flash_spi_erase_info_t Flash_Info_E;
uint32 t
                       loop_cnt = 0;
Flash_Info_E.addr = 0;
Flash_Info_E.mode = FLASH_SPI_MODE_S_ERASE;
ret = R FLASH SPI Erase(FLASH SPI DEV0, &Flash Info E);
if (FLASH SPI SUCCESS > ret)
 /* Error */
loop cnt = FLASH SE BUSY WAIT;
mode = FLASH SPI MODE ERASE POLL;
do
{
   /* FLASH is busy.
     User application can perform other processing while flash is busy. */
  ret = R FLASH SPI Polling(FLASH SPI DEV0, mode);
  if (FLASH SPI SUCCESS BUSY != ret)
     /* FLASH is ready or error. */
     break;
  loop cnt--;
  while (0 != loop_cnt);
if ((0 == loop cnt) || (FLASH SPI SUCCESS > ret))
  /* Error */
}
```

# **Special Notes**

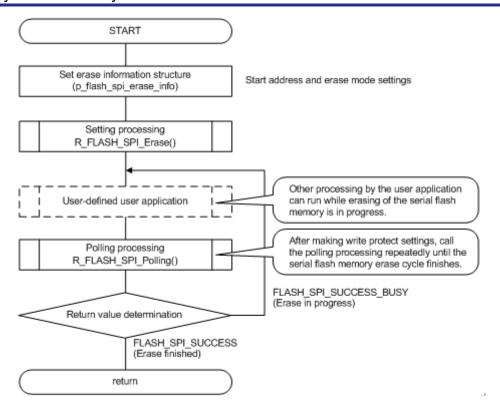


Figure 3.3 R\_FLASH\_SPI\_Erase() Processing Example

# R\_FLASH\_SPI\_Polling()

This function is used to perform polling to determine if a write or erase operation has finished.

### **Format**

## **Return Values**

```
FLASH_SPI_SUCCESS /* Normal end, and write finished */
FLASH_SPI_SUCCESS_BUSY /* Normal end, and write in progress */
FLASH_SPI_ERR_PARAM /* Parameter error */
FLASH_SPI_ERR_HARD /* Hardware error */
FLASH_SPI_ERR_OTHER /* Other task has acquired clock synchronous single master control software resources, or other error */
```

## **Properties**

Prototype declarations are contained in r flash spi if.h.

# **Description**

Determines whether or not a write or erase operation has finished.

## Example

Refer to figure 3.1 or figure 3.2.

## **Special Notes**

R\_FLASH\_SPI\_Polling() can be called at any time specified by the user. This makes it possible for the user application to perform other processing while a write cycle is in progress.

# R\_FLASH\_SPI\_Read\_ID()

This function is used to read ID information.

### **Format**

```
flash_spi_status_t R_FLASH_SPI_Read_ID(
    uint8_t devno,
    uint8_t * p_data
)
```

## **Parameters**

devno

Device number (0, 1)

\* p data

ID information storage buffer. The size differs depending on the serial flash memory product used. Refer to the following and check the contents of the read buffer.

- <MX25L, MX66L, or MX25R family serial NOR flash memory of Macronix International Co., Ltd.> The function reads the manufacturer ID and device ID. Specify 3 bytes as a read buffer.
  - (1) Manufacturer ID (1 byte)
  - (2) Device ID (2 bytes)
- <AT25QF family serial NOR flash memory of Dialog Semiconductor Plc.>

The function reads the manufacturer ID and device ID. Specify 3 bytes as a read buffer.

- (1) Manufacturer ID (1 byte)
- (2) Device ID (2 bytes)

## **Return Values**

```
FLASH_SPI_SUCCESS /* Successful operation */
FLASH_SPI_ERR_PARAM /* Parameter error */
FLASH_SPI_ERR_HARD /* Hardware error */
FLASH_SPI_ERR_OTHER /* Other task has acquired clock synchronous single master control software resources, or other error */
```

### **Properties**

Prototype declarations are contained in r\_flash\_spi\_if.h.

## **Description**

Stores ID information for the serial flash memory in p\_data.

## Example

```
flash_spi_status_t ret = FLASH_SPI_SUCCESS;
uint8_t gID[4];

ret = R_FLASH_SPI_Read_ID(FLASH_SPI_DEV0, &gID[0]);
```

## **Special Notes**

# R\_FLASH\_SPI\_GetMemoryInfo()

This function is used to fetch the serial flash memory size information.

## **Format**

```
flash_spi_status_t R_FLASH_SPI_GetMemoryInfo(
    uint8_t devno,
    flash_spi_mem_info_t * p_flash_spi_mem_info
)
```

## **Parameters**

devno

```
Device number (0, 1) * p_flash_spi_mem_info
```

Serial flash memory size information structure. Use a structure address aligned with a 4-byte boundary.

mem\_size

Maximum memory size wpag\_size

Page size

## **Return Values**

```
FLASH_SPI_SUCCESS /* Successful operation */
FLASH_SPI_ERR_PARAM /* Parameter error */
```

## **Properties**

Prototype declarations are contained in r\_flash\_spi\_if.h.

## **Description**

Fetches serial flash memory size information for the device number specified by the argument devno.

## **Example**

```
flash_spi_status_t ret = FLASH_SPI_SUCCESS;
flash_spi_mem_info_t Flash_MemInfo;

ret = R_FLASH_SPI_GetMemoryInfo(FLASH_SPI_DEV0, &Flash_MemInfo);
```

# **Special Notes**

None

# R\_FLASH\_SPI\_Read\_Configuration()

This function is used to read the configuration register(s). It is a dedicated API function for MX25L, MX66L, or MX25R family serial NOR flash memory of Macronix International Co., Ltd.

### **Format**

```
flash_spi_status_t R_FLASH_SPI_Read_Configuration (
     uint8_t devno,
     uint8_t * p_config
)
```

### **Parameters**

devno

Device number (0, 1)

\* p\_config

Configuration register storage buffer. The size differs depending on the serial NOR flash memory product used. Refer to the following and check the contents of the read buffer.

- <MX25L, MX66L or MX25R family serial NOR flash memory of Macronix International Co., Ltd.> The function reads the configuration register. Specify 1 byte as a read buffer.
- <MX25L, MX66L or MX25R family serial NOR flash memory of Macronix International Co., Ltd.>
   The function reads configuration register 1 and configuration register 2. Specify 2 bytes as a read buffer.

## **Return Values**

```
FLASH_SPI_SUCCESS /* Successful operation */
FLASH_SPI_ERR_PARAM /* Parameter error */
FLASH_SPI_ERR_HARD /* Hardware error */
FLASH_SPI_ERR_OTHER /* Other task has acquired clock synchronous single master control software resources, or other error */
```

## **Properties**

Prototype declarations are contained in r flash spi if.h.

### Description

Reads the configuration register(s) of the serial NOR Flash memory and stores the contents in p\_config. The data stored in p\_config is listed below. Note that, depending on the serial NOR flash memory product used, there may be function allocations or reserved bits. For details, refer to the data sheet of the serial NOR flash memory product used.

<MX25L, MX66L or MX25R family serial NOR flash memory of Macronix International Co., Ltd.>

**Table 3.5 Configuration Register Listing** 

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
DC1	DC0	4 BYTE	PBE	ТВ	ODS 2	ODS 1	ODS 0
(dummy	(dummy		(preamble bit	(top/bottom	(output	(output	(output
cycle 1)	cycle 0)		enable)	selected)	driver	driver	driver
					strength)	strength)	strength)
*	*	0 = 3-byte	0 = disable	0 = top area	*	*	*
		address mode	1 = enable	protect			
		1 = 4-byte		1 = bottom			
		address mode		area protect			
		(default = 0)		(default = 0)			
volatile bit	volatile bit	volatile bit	volatile bit	OTP	volatile bit	volatile bit	volatile bit

Note: \* See the specification of the Flash memory.



• <MX25R family serial NOR flash memory of Macronix International Co., Ltd.>

**Table 3.6 Configuration Register 2 Listing** 

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	L/H switch	Reserved
х	х	х	х	х	х	0 = low	х
						power mode (default) 1 = high performance mode	
х	х	х	х	х	х	volatile bit	х

## Example

```
flash_spi_status_t         ret = FLASH_SPI_SUCCESS;
uint8_t         gConfig[4];         /* the buffer boundary (4-byte unit) */
ret = R_FLASH_SPI_Read_Configuration(FLASH_SPI_DEV0, &gConfig[0]);
```

# **Special Notes**

# R\_FLASH\_SPI\_Write\_Configuration()

This function is used to write the configuration register(s). It is a dedicated API function for MX25L, MX66L, or MX25R family serial NOR flash memory of Macronix International Co., Ltd.

### **Format**

Note that the configuration of the structure differs depending on the serial NOR flash memory product used. Refer to the following when making settings. Also, refer to "Description" for setting values.

• <MX25L or MX66L family serial NOR flash memory of Macronix International Co., Ltd.>

The value set in p reg ->config1 is written to the configuration register.

The setting of p reg->config2 is ignored.

Configuration register 2 setting data

<MX25R family serial NOR flash memory of Macronix International Co., Ltd.>

The value set in p\_reg->config1 is written to the configuration register 1. The value set in p\_reg->config2 is written to the configuration register 2.

## **Return Values**

```
FLASH_SPI_SUCCESS /* Successful operation */
FLASH_SPI_ERR_PARAM /* Parameter error */
FLASH_SPI_ERR_HARD /* Hardware error */
FLASH_SPI_ERR_OTHER /* Other task has acquired clock synchronous single master control software resources, or other error */
```

# **Properties**

Prototype declarations are contained in r flash spi if.h.

## Description

The values set in p\_reg->config1 and p\_reg->config2 are written to the configuration register. Refer to the information below when making settings to p\_reg->config1 and p\_reg->config2. Note that, depending on the serial NOR flash memory product used, there may be function allocations or reserved bits. For details, refer to the data sheet of the serial NOR flash memory product used.

Configuration register
Bits 7 to 6: DC1-DC0 (Dummy cycle)
See the specification of the Flash memory.
Bit 5: 4BYTE (4BYTE Indicator)
1: 4-byte address mode
0: 3-byte address mode
Bit 4: PBE (Preamble bit Enable)
1: Enable



0: Disable

Bit 3: TB (Top/Bottom)

1: Bottom area protect

0: Top area protect

Bits 2 to 0: ODS2-ODS0 (Output driver strength) See the specification of the Flash memory.

Configuration register 2 Bits 7 to 2: Reserved Bit 1: L/H Switch

1: High performance mode

0: Low power mode

Bit 0: Reserved

Before calling this user API function, read the value of the configuration registers, change the values of only the bits that need to be overwritten, and then make settings to p\_reg->config1 and p\_reg->config2. After processing finishes, read the configuration registers to confirm that the written values are correct. The 4BYTE bit is read-only, and its setting is ignored. This bit can be set to 1 by using R FLASH SPI Set 4byte Address Mode().

When this user API function completes successfully, the serial flash memory transitions to a write cycle. Do not fail to confirm write completion with R\_FLASH\_SPI\_Polling(). If the next read or write processing starts when a previous write cycle is in progress, the serial flash memory will not accept the new processing. R\_FLASH\_SPI\_Polling() can be called at any time specified by the user. This allows a user application to perform other processing while a write cycle is in progress. See figure 3.4 for details.

```
#define FLASH WR BUSY WAIT (uint32 t)(40) /* 40 * 1ms = 40ms */
flash spi status t ret = FLASH SPI SUCCESS;
uint32 t
                   loop cnt = 0;
flash spi reg info t Reg;
uint8 t
                    gConfig[4]; /* the buffer boundary (4-byte unit) */
ret = R FLASH SPI Read Configuration(FLASH SPI DEV0, &gConfig[0]);
if (FLASH SPI SUCCESS > ret)
  /* Error */
}
Reg.config1 = (gConfig[0] \mid 0x10); /* Set Preamble bit Enable */
ret = R FLASH SPI Write Configuration(FLASH SPI DEV0, &Reg);
if (FLASH SPI SUCCESS > ret)
  /* Error */
}
loop cnt = FLASH WR BUSY WAIT;
mode = FLASH SPI MODE REG WRITE POLL;
do
{
   /* FLASH is busy.
     User application can perform other processing while flash is busy. */
  ret = R FLASH SPI Polling(FLASH SPI DEV0, mode);
   if (FLASH SPI SUCCESS BUSY != ret)
     /* FLASH is ready or error. */
     break;
  loop cnt--;
  while (0 != loop cnt);
if ((0 == loop cnt) || (FLASH SPI SUCCESS > ret))
  /* Error */
}
```

## **Special Notes**

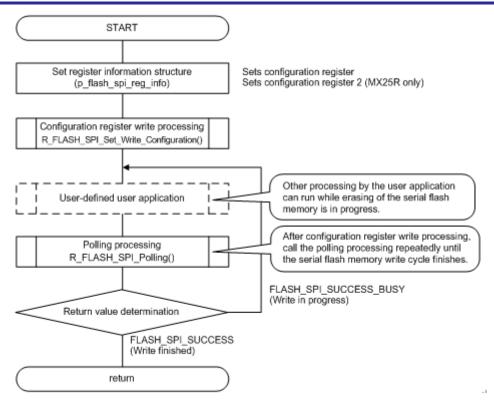


Figure 3.4 R\_FLASH\_SPI\_Write\_Configuration() Processing Example

# R\_FLASH\_SPI\_Write\_Status()

This function is used to write the status register 1. It is a dedicated API function for AT25QF family serial NOR flash memory of Dialog Semiconductor Plc.

```
flash_spi_status_t R_FLASH_SPI_Write_Status(
    uint8 t devno,
    uint8 t*p reg
)
Parameters
```

devno

Device number (0, 1)

\*preg

Status register setting data buffer

## **Return Values**

```
FLASH_SPI_SUCCESS
                                /* Successful operation */
FLASH SPI ERR PARAM
                                /* Parameter error */
FLASH SPI ERR HARD
                                /* Hardware error */
FLASH SPI ERR OTHER
                                /* Other task has acquired clock synchronous single
                                  master control software resources, or other error */
```

# **Properties**

Prototype declarations are contained in r flash spi if.h.

## **Description**

The values set in p\_reg is written to the status register 1. Note that, depending on the serial NOR flash memory product used, there may be function allocations or reserved bits. For details, refer to the data sheet of the serial NOR flash memory product used.

```
Status Register 1
Bit 7: Status Register Protection bit 0
    See the specification of the Flash memory.
Bit 6: Block Protection
    See the specification of the Flash memory.
Bit 5: TB (Top/Bottom)
    See the specification of the Flash memory.
Bits 4 to 2: BP2-BP0 (Block Protection bit)
    See the specification of the Flash memory.
```

Before calling this user API function, read the value of the status register 1, change the values of only the bits that need to be overwritten. After processing finishes, read the status register 1 to confirm that the written values are correct.

When this user API function completes successfully, the serial flash memory transitions to a write cycle. Do not fail to confirm write completion with R\_FLASH\_SPI\_Polling(). If the next read or write processing starts when a previous write cycle is in progress, the serial flash memory will not accept the new processing. R FLASH SPI Polling() can be called at any time specified by the user. This allows a user application to perform other processing while a write cycle is in progress.

```
#define FLASH WR BUSY WAIT (uint32 t)(40) /* 40 * 1ms = 40ms */
flash spi status t ret = FLASH SPI SUCCESS;
uint32 t
                  loop cnt = 0;
uint8 t
                   qStat;
uint8 t
                   Req;
ret = R FLASH SPI Read Status(FLASH SPI DEV0, &gStat);
if (FLASH SPI SUCCESS > ret)
  /* Error */
}
Reg = (gStat | 0x10);
ret = R FLASH SPI Write Status(FLASH SPI DEV0, &Reg);
if (FLASH SPI SUCCESS > ret)
  /* Error */
}
loop cnt = FLASH WR BUSY WAIT;
mode = FLASH SPI MODE REG WRITE POLL;
do
{
   /* FLASH is busy.
     User application can perform other processing while flash is busy. */
  ret = R FLASH SPI Polling(FLASH SPI DEV0, mode);
   if (FLASH SPI SUCCESS BUSY != ret)
     /* FLASH is ready or error. */
     break;
  loop cnt--;
  while (0 != loop cnt);
if ((0 == loop_cnt) || (FLASH_SPI SUCCESS > ret))
  /* Error */
}
```

## **Special Notes**

# R FLASH SPI\_Write\_Status2()

This function is used to write the status register 2. It is a dedicated API function for AT25QF family serial NOR flash memory of Dialog Semiconductor Plc.

```
flash_spi_status_t R_FLASH_SPI_Write_Status2(
    uint8 t devno,
    uint8 t*p reg
)
```

### **Parameters**

devno

Device number (0, 1)

\*preg

Status register setting data buffer

## **Return Values**

```
FLASH_SPI_SUCCESS
                                /* Successful operation */
FLASH SPI ERR PARAM
                               /* Parameter error */
FLASH SPI ERR HARD
                               /* Hardware error */
FLASH SPI ERR OTHER
                                /* Other task has acquired clock synchronous single
                                 master control software resources, or other error */
```

# **Properties**

Prototype declarations are contained in r flash spi if.h.

## **Description**

The values set in p\_reg is written to the status register 2. Note that, depending on the serial NOR flash memory product used, there may be function allocations or reserved bits. For details, refer to the data sheet of the serial NOR flash memory product used.

Status Register 2

Bits 7: Complement Block Protection

See the specification of the Flash memory.

Bit 6: Lock Security Register 3

- 1: Security Register page-3 cannot be erased/programmed.
- 0: Security Register page-3 is not locked

Bit 5: Lock Security Register 2

- 1: Security Register page-2 cannot be erased/programmed.
- 0: Security Register page-2 is not locked

Bit 4: Lock Security Register 1

- 1: Security Register page-1 cannot be erased/programmed.
- 0: Security Register page-1 is not locked

Bits 1: Quad Enable

- 1: HOLD and WP are I/O pins
- 0: HOLD and WP function normally.

Before calling this user API function, read the value of the status register 2, change the values of only the bits that need to be overwritten. After processing finishes, read the status register 2 to confirm that the written values are correct.

When this user API function completes successfully, the serial flash memory transitions to a write cycle. Do not fail to confirm write completion with R FLASH SPI Polling(). If the next read or write processing starts when a previous write cycle is in progress, the serial flash memory will not accept the new processing. R FLASH SPI Polling() can be called at any time specified by the user. This allows a user application to perform other processing while a write cycle is in progress.



```
\#define FLASH_WR_BUSY_WAIT (uint32_t)(40) /* 40 * 1ms = 40ms */
flash spi status t ret = FLASH SPI SUCCESS;
uint32_t loop_cnt = 0;
uint8 t
                   qStat;
uint8 t
                   Reg;
ret = R FLASH SPI Read Status2(FLASH SPI DEV0, & gStat);
if (FLASH SPI SUCCESS > ret)
  /* Error */
}
Reg = (gStat \mid 0x10);
ret = R_FLASH_SPI_Write_Status2(FLASH_SPI_DEV0, &Reg);
if (FLASH SPI SUCCESS > ret)
  /* Error */
}
loop cnt = FLASH WR BUSY WAIT;
mode = FLASH_SPI_MODE_REG_WRITE_POLL;
do
{
   /* FLASH is busy.
     User application can perform other processing while flash is busy. */
   ret = R FLASH SPI Polling(FLASH SPI DEV0, mode);
  if (FLASH SPI SUCCESS BUSY != ret)
     /* FLASH is ready or error. */
     break;
  loop cnt--;
  while (0 != loop cnt);
if ((0 == loop cnt) || (FLASH SPI SUCCESS > ret))
  /* Error */
```

## **Special Notes**

# R\_FLASH\_SPI\_Write\_Status3()

This function is used to write the status register 3. It is a dedicated API function for AT25QF family serial NOR flash memory of Dialog Semiconductor Plc.

### **Format**

```
flash_spi_status_t R_FLASH_SPI_Write_Status2(
    uint8_t devno,
    uint8_t * p_reg
)

Parameters
devno
    Device number (0, 1)
* p_reg
```

Status register setting data buffer

# **Return Values**

```
FLASH_SPI_SUCCESS /* Successful operation */
FLASH_SPI_ERR_PARAM /* Parameter error */
FLASH_SPI_ERR_HARD /* Hardware error */
FLASH_SPI_ERR_OTHER /* Other task has acquired clock synchronous single master control software resources, or other error */
```

# **Properties**

Prototype declarations are contained in r\_flash\_spi\_if.h.

## **Description**

The values set in p\_reg is written to the status register 3. Note that, depending on the serial NOR flash memory product used, there may be function allocations or reserved bits. For details, refer to the data sheet of the serial NOR flash memory product used.

```
Status Register 3
Bit 7: Reserved
Bits 6 to 5: DRV[1:0] (Drive strength)
11: Auto (7 pF based on VCC level)
10: 50% (15 pF)
01: 75% (22 pF)
00: 100% (30 pF)
Bits 4 to 0: Reserved
```

Before calling this user API function, read the value of the status register 3, change the values of only the bits that need to be overwritten. After processing finishes, read the status register 3 to confirm that the written values are correct.

When this user API function completes successfully, the serial flash memory transitions to a write cycle. Do not fail to confirm write completion with R\_FLASH\_SPI\_Polling(). If the next read or write processing starts when a previous write cycle is in progress, the serial flash memory will not accept the new processing. R\_FLASH\_SPI\_Polling() can be called at any time specified by the user. This allows a user application to perform other processing while a write cycle is in progress.

```
#define FLASH WR BUSY WAIT (uint32 t)(40) /* 40 * 1ms = 40ms */
flash spi status t ret = FLASH SPI SUCCESS;
uint32 t
                  loop cnt = 0;
uint8 t
                   qStat;
uint8 t
                   Req;
ret = R FLASH SPI Read Status3(FLASH SPI DEV0, & gStat);
if (FLASH SPI SUCCESS > ret)
  /* Error */
}
Reg = (gStat | 0x60); /* Set auto drive strength */
ret = R FLASH SPI Write Status3(FLASH SPI DEV0, &Reg);
if (FLASH SPI SUCCESS > ret)
  /* Error */
}
loop cnt = FLASH WR BUSY WAIT;
mode = FLASH SPI MODE REG WRITE POLL;
do
{
  /* FLASH is busy.
     User application can perform other processing while flash is busy. */
  ret = R FLASH SPI Polling(FLASH SPI DEV0, mode);
  if (FLASH SPI SUCCESS BUSY != ret)
     /* FLASH is ready or error. */
     break;
  loop cnt--;
  while (0 != loop cnt);
if ((0 == loop_cnt) || (FLASH_SPI SUCCESS > ret))
  /* Error */
}
```

## **Special Notes**

# R\_FLASH\_SPI\_Set\_4byte\_Address\_Mode()

This function is used to set the address mode to 4-byte address mode. It is a dedicated API function for MX25L, MX66L, or MX25R family serial NOR flash memory of Macronix International Co., Ltd.

### **Format**

```
flash_spi_status_t R_FLASH_SPI_Set_4byte_Address_Mode(
     uint8_t devno
)
```

## **Parameters**

devno

Device number (0, 1)

```
Return Values

FLASH_SPI_SUCCESS /* Successful operation */

FLASH_SPI_ERR_PARAM /* Parameter error */

FLASH_SPI_ERR_HARD /* Hardware error */

FLASH_SPI_ERR_OTHER /* Other task has acquired clock synchronous single master control software resources, or other error */
```

## **Properties**

Prototype declarations are contained in r\_flash\_spi\_if.h.

## **Description**

• <MX25L, MX66L, or MX25R family serial NOR flash memory of Macronix International Co., Ltd.> Issues the EN4B (0xb7) command to set the 4BYTE bit in the configuration register to 1.

## Example

```
flash_spi_status_t ret = FLASH_SPI_SUCCESS;

ret = R_FLASH_SPI_Set_4byte_Address_Mode(FLASH_SPI_DEV0);
```

# **Special Notes**

# R\_FLASH\_SPI\_Read\_Security()

This function is used to read the security register. It is a dedicated API function for MX25L, MX66L, or MX25R family serial NOR flash memory of Macronix International Co., Ltd.

\* p scur

```
eepr_status_t R_FLASH_SPI_Read_Security
    uint8 t devno,
    uint8 t*p scur
)
Parameters
devno
   Device number (0, 1)
```

Security register storage buffer (size: 1 byte)

## **Return Values**

```
FLASH_SPI_SUCCESS
                                /* Successful operation */
FLASH SPI ERR PARAM
                               /* Parameter error */
FLASH SPI ERR HARD
                               /* Hardware error */
FLASH SPI ERR OTHER
                               /* Other task has acquired clock synchronous single
                                 master control software resources, or other error */
```

# **Properties**

Prototype declarations are contained in r\_flash\_spi\_if.h.

## **Description**

Reads the security register and stores the contents in p\_scur.

The information stored in p scur is listed below. Note that, depending on the serial NOR flash memory product used, there may be function allocations or reserved bits. For details, refer to the data sheet of the serial NOR flash memory product used.

```
Bit 7: WPSEL
    1: Individual mode
    0: Normal WP mode
Bit 6: E FAIL
    1: Erase failed
    0: Erase succeed
Bit 5: P FAIL
    1: Program failed
    0: Program succeed
Bit 4: Reserved
Bit 3: ESB (Erase Suspend Bit)
    1: Erase Suspended
    0: Erase is not suspended
Bit 2: PSB (Program Suspend Bit)
    1: Program Suspended
    0: Program is not suspended
Bit 1: LDSO (Indicate if lock-down)
    1: Lock-down (Cannot program/erase OTP)
    0: Not lock-down
Bit 0: Secured OTP indicator
    1: Factory lock
    0: Non-factory lock.
```



If P FAIL is set to 1, it is cleared to 0 the next time a programming operation succeeds. If E FAIL is set to 1, it is cleared to 0 the next time an erase operation succeeds.

```
flash_spi_status_t ret = FLASH_SPI_SUCCESS;
uint8_t scur = 0;

ret = R FLASH SPI Read Security(FLASH SPI DEV0, &dcur);
```

# **Special Notes**

# R\_FLASH\_SPI\_Read\_Data\_Security\_Page()

This function is used to read data from the security registers. It is a dedicated API function for AT25QF family serial NOR flash memory of Dialog Semiconductor Plc.

### **Format**

```
flash_spi_status_t R_FLASH_SPI_Read_Data_Security_Page(
    uint8_t devno,
    flash_spi_info_t * p_flash_spi_info
)
```

### **Parameters**

devno

Device number (0, 1)

\* p\_flash\_spi\_info

Serial flash memory information structure. Use a structure address aligned with a 4-byte boundary.

Specify the start address of the security register.

cnt

Specify the read byte count. The allowable setting range is 1 to 256. A setting of 0 causes an error to be returned.

data cnt

Read byte count (Used by the control software, so setting by the user is prohibited.)

\*p\_data

Specify the address of the read data storage buffer. Use a buffer address aligned with a 4-byte boundary.

## **Return Values**

```
FLASH_SPI_SUCCESS /* Successful operation */
FLASH_SPI_ERR_PARAM /* Parameter error */
FLASH_SPI_ERR_HARD /* Hardware error */
FLASH_SPI_ERR_OTHER /* Other task has acquired clock synchronous single master control software resources, or other error */
```

## **Properties**

Prototype declarations are contained in r\_flash\_spi\_if.h.

# **Description**

Reads the specified number of bytes of data from the specified address in the security register and stores the data in p\_data.

The maximum read address is the page size -1.

Rollover read operations are not supported. After the end address is read, processing ends. It is then necessary to reset the address and call this API function again.

FLASH\_SPI\_ERR\_PARAM is returned if the total value of the read byte count, cnt, and specified address, addr. exceeds the maximum read address.

DMAC transfer or DTC transfer occurs when the transfer size conditions of the clock synchronous single master control software are matched. Otherwise, operation switches to software transfer.

# **Special Notes**

To speed up data transfers, align the start address with a 4-byte boundary when specifying data storage buffer pointers.

The clock synchronous single master control software resources are acquired at the start of the processing, and the resources are released and the end of the processing.

This API function is omitted in QSPIX Memory Mapped Mode.

# R\_FLASH\_SPI\_Write\_Data\_Security\_Page()

This function is used to write data to the security register pages in single-page units. It is a dedicated API function for AT25QF family serial NOR flash memory of Dialog Semiconductor Plc.

### **Format**

```
flash_spi_status_t R_FLASH_SPI_Write_Data_Security_Page(
    uint8_t devno,
    flash_spi_info_t * p_flash_spi_info
)
```

### **Parameters**

devno

Device number (0, 1)

\* p\_flash\_spi\_info

Serial flash memory information structure. Use a structure address aligned with a 4-byte boundary.

Specify the start address of the security register.

cnt

Specify the write byte count. The allowable setting range is 1 to 256. A setting of 0 causes an error to be returned.

data cnt

Write byte count (Used by the control software, so setting by the user is prohibited.)

\*p\_data

Specify the address of the write data storage buffer.

## **Return Values**

```
FLASH_SPI_SUCCESS /* Successful operation */
FLASH_SPI_ERR_PARAM /* Parameter error */
FLASH_SPI_ERR_HARD /* Hardware error */
FLASH_SPI_ERR_OTHER /* Other task has acquired clock synchronous single master control software resources, or other error */
```

# **Properties**

Prototype declarations are contained in r\_flash\_spi\_if.h.

## **Description**

Writes the specified number of bytes of data (up to a maximum size of 1 page) in p\_data to the security register pages, starting from the specified address.

When writing a large volume of data, communication is divided into page units. This prevents a situation in which other processing is not possible while communication is in progress.

Writing to the security register pages is only possible when they are not locked. It is not possible to write to a locked page. Attempting to do so returns the error FLASH SPI ERR WP.

The maximum write byte count (cnt) setting value is the capacity of the security register page size.

FLASH\_SPI\_ERR\_PARAM is returned if the total value of the write byte count, cnt, and specified address, addr, exceeds the maximum write address.

DMAC transfer or DTC transfer occurs when the transfer size conditions of the clock synchronous single master control software are matched. Otherwise, operation switches to software transfer.

```
flash spi status t    ret = FLASH SPI SUCCESS;
flash_spi_info_t Flash_Info_W;
uint32_t buf1[128/sizeof(uint32_t)];
uint32 t
                                /* the buffer boundary (4-byte unit) */
uint32 t
           loop cnt = 0;
Flash_Info_W.addr = 0;
Flash_Info_W.cnt = 128;
Flash Info W.p data = (uint8 t *) \&buf1[0];
do
   ret = R FLASH SPI Write Data Security Page (FLASH SPI DEVO, &Flash Info W);
   if (FLASH SPI SUCCESS > ret)
      /* Error */
   }
   loop cnt = FLASH PP BUSY WAIT;
   mode = FLASH SPI MODE PROG POLL;
   do
   {
      /* FLASH is busy.
        User application can perform other processing while flash is busy. */
        ret = R FLASH SPI Polling(FLASH SPI DEV0, mode);
         if (FLASH SPI SUCCESS BUSY != ret)
            /* FLASH is ready or error. */
           break;
         loop cnt--;
        wait timer(0, 1);     /* 1ms */
   while (0 != loop cnt);
while (0 != Flash Info W.cnt);
if ((0 == loop cnt) || (FLASH SPI SUCCESS > ret))
   /* Error */
}
```

## **Special Notes**

To speed up data transfers, align the start address with a 4-byte boundary when specifying data storage buffer pointers.

# R\_FLASH\_SPI\_Quad\_Enable()

This function is used to enable quad mode. It is a dedicated API function for MX25L, MX66L, or MX25R family serial NOR flash memory of Macronix International Co., Ltd and AT25QF family serial NOR flash memory of Dialog Semiconductor Plc.

## **Format**

```
flash_spi_status_t R_FLASH_SPI_Quad_Enable(
    uint8_t devno
)
```

# **Parameters**

devno

Device number (0, 1)

## **Return Values**

```
FLASH_SPI_SUCCESS /* Successful operation */
FLASH_SPI_ERR_PARAM /* Parameter error */
FLASH_SPI_ERR_HARD /* Hardware error */
FLASH_SPI_ERR_OTHER /* Other task has acquired clock synchronous single master control software resources, or other error */
```

## **Properties**

Prototype declarations are contained in r flash spi if.h.

## **Description**

Sets the quad enable (QE) bit in the status register to 1 to enable quad mode.

To use quad mode, first call this function.

After processing finishes, read the status register to confirm that the value of the QE bit is 1.

The quad enable (QE) bit is a non-volatile bit. Once quad mode has been enabled, it is necessary to run R\_FLASH\_SPI\_Quad\_Disable() to disable quad mode.

When this user API function completes successfully, the serial flash memory transitions to a write cycle. Do not fail to confirm write completion with R\_FLASH\_SPI\_Polling(). If the next read or write processing starts when a previous write cycle is in progress, the serial flash memory will not accept the new processing. R\_FLASH\_SPI\_Polling() can be called at any time specified by the user. This allows a user application to perform other processing while a write cycle is in progress. See figure 3.5 for details.

```
\#define FLASH\_WR\_BUSY\_WAIT (uint32\_t)(40) /* 40 * 1ms = 40ms */
flash spi status t ret = FLASH SPI SUCCESS;
uint32 t
                      loop cnt = 0;
flash spi poll mode t mode;
ret = R FLASH SPI Quad Enable(FLASH SPI DEV0);
if (FLASH SPI SUCCESS > ret)
{
   /* Error */
}
loop cnt = FLASH WR BUSY WAIT;
mode = FLASH SPI MODE REG WRITE POLL;
   /* FLASH is busy.
     User application can perform other processing while flash is busy. */
  ret = R FLASH SPI Polling(FLASH SPI DEV0, mode);
 if (FLASH SPI SUCCESS BUSY != ret)
     /* FLASH is ready or error. */
     break;
  loop cnt--;
  while (0 != loop cnt);
if ((0 == loop cnt) || (FLASH SPI SUCCESS > ret))
   /* Error */
}
```

## **Special Notes**

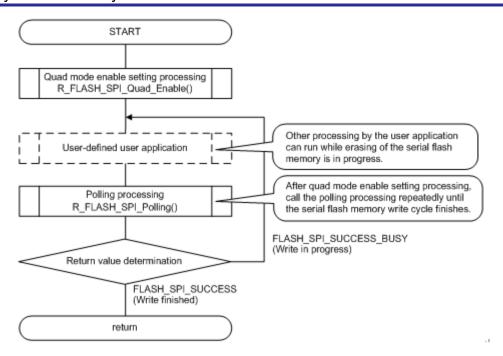


Figure 3.5 R\_FLASH\_SPI\_Quad\_Enable() Processing Example

# R FLASH\_SPI\_Quad\_Disable()

This function is used to disable quad mode. It is a dedicated API function for MX25L, MX66L, or MX25R family serial NOR flash memory of Macronix International Co., Ltd and AT25QF family serial NOR flash memory of Dialog Semiconductor Plc.

#### **Format**

```
flash_spi_status_t R_FLASH_SPI_Quad_Disable(
    uint8_t devno
)
```

#### **Parameters**

devno

Device number (0, 1)

#### **Return Values**

```
FLASH_SPI_SUCCESS /* Successful operation */
FLASH_SPI_ERR_PARAM /* Parameter error */
FLASH_SPI_ERR_HARD /* Hardware error */
FLASH_SPI_ERR_OTHER /* Other task has acquired clock synchronous single master control software resources, or other error */
```

#### **Properties**

Prototype declarations are contained in r\_flash\_spi\_if.h.

#### Description

Clears the quad enable (QE) bit in the status register to 0 to cancel quad mode.

After processing finishes, read the status register to confirm that the value of the QE bit is 0.

The quad enable (QE) bit is a non-volatile bit. Once quad mode has been enabled, it is necessary to run this user API function to disable quad mode.

When this user API function completes successfully, the serial flash memory transitions to a write cycle. Do not fail to confirm write completion with R\_FLASH\_SPI\_Polling(). If the next read or write processing starts when a previous write cycle is in progress, the serial flash memory will not accept the new processing. R\_FLASH\_SPI\_Polling() can be called at any time specified by the user. This allows a user application to perform other processing while a write cycle is in progress. See figure 3.6 for details.

## **Example**

```
#define FLASH_WR_BUSY_WAIT (uint32_t)(40)
                                         /* 40 * 1ms = 40ms */
flash spi status t ret = FLASH SPI SUCCESS;
uint32 t
                     loop cnt = 0;
flash spi poll mode t mode;
ret = R FLASH SPI Quad Disable(FLASH SPI DEV0);
if (FLASH SPI SUCCESS > ret)
{
  /* Error */
}
loop cnt = FLASH WR BUSY WAIT;
mode = FLASH SPI MODE REG WRITE POLL;
   /* FLASH is busy.
     User application can perform other processing while flash is busy. */
  ret = R FLASH SPI Polling(FLASH SPI DEV0, mode);
 if (FLASH SPI SUCCESS BUSY != ret)
     /* FLASH is ready or error. */
     break;
  loop cnt--;
  while (0 != loop cnt);
if ((0 == loop cnt) || (FLASH SPI SUCCESS > ret))
  /* Error */
}
```

### **Special Notes**

The clock synchronous single master control software resources are acquired at the start of the processing, and the resources are released and the end of the processing.

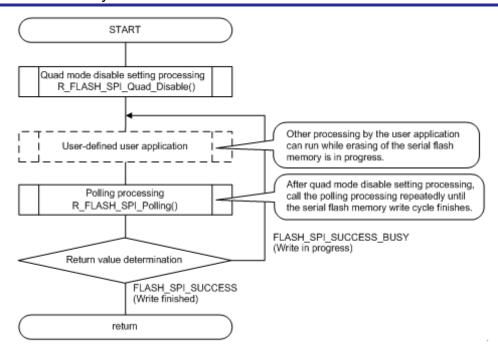


Figure 3.6 R\_FLASH\_SPI\_Quad\_Disable() Processing Example

# R\_FLASH\_SPI\_GetVersion()

This function is used to fetch the serial flash memory version information.

#### **Format**

uint32\_t R\_FLASH\_SPI\_GetVersion(void)

#### **Parameters**

None

#### **Return Values**

Version number

Upper 2 bytes: major version, lower 2 bytes: minor version

## **Properties**

Prototype declarations are contained in r\_flash\_spi\_if.h.

## **Description**

Returns the version information.

## **Example**

```
uint32 t version;
version = R FLASH SPI GetVersion();
```

## **Special Notes**

None

# R\_FLASH\_SPI\_Set\_LogHdlAddress()

This function specifies the handler address for the LONGQ FIT module. Call this function when using error log acquisition processing.

#### **Format**

```
flash_spi_status_t R_FLASH_SPI_Set_LogHdlAddress(
    uint32_t user_long_que
)
```

### **Parameters**

user long que

Specify the handler address of the LONGQ FIT module.

#### **Return Values**

```
FLASH_SPI_SUCCESS /* Successful operation */
```

## **Properties**

Prototype declarations are contained in r\_flash\_spi\_if.h.

## Description

Sets the handler address of the LONGQ FIT module in the serial flash memory control software and the clock synchronous single master control software used by the specified device.

This is preparatory processing to enable fetching of error logs using the LONGQ FIT module. Run this function before calling R FLASH SPI Open().

## **Example**

```
#define ERR_LOG_SIZE (16)
#define USER LONGQ IGN OVERFLOW
                                (1)
flash spi status t ret = FLASH SPI SUCCESS;
ret longq = LONGQ SUCCESS;
longq err t
             p_user_long_que;
longq_hdl_t
                long que hndl address = 0;
uint32 t
/* Open LONGQ module. */
ret longq = R LONGQ Open(&MtlLogTbl[0],
                      ERR LOG SIZE,
                       USER LONGQ IGN OVERFLOW,
                       &p user long que
);
long_que_hndl_address = (uint32_t)p_user_long_que;
R FLASH SPI Set LogHdlAddress(long que hndl address);
```

#### **Special Notes**

Add the LONGQ FIT module, which is available separately, to your project.

Enable the option #define FLASH\_SPI\_CFG\_LONGQ\_ENABLE in r\_flash\_spi\_config.h. Also, enable #define xxx\_LONGQ\_ENABLE in the clock synchronous single master control software used by the specified device. In the LONGQ FIT module, set the ignore\_overflow argument of R\_LONGQ\_Open() to 1. This allows the error log buffer to be used as a ring buffer.

## R\_FLASH\_SPI\_Log()

This function fetches the error log. When an error occurs, call this function immediately before user processing ends.

#### **Format**

```
uint32_t R_FLASH_SPI_Log(
    uint32_t flg,
    uint32_t fid,
    uint32_t line
)

Parameters
flg
    Set this to 0x00000001 (fixed value).
fid
    Set this to 0x0000003f (fixed value).
line
    Set this to 0x0001ffff (fixed value).
```

#### **Return Values**

```
0 /* Successful operation */
1 /* Error */
```

## **Properties**

Prototype declarations are contained in r flash spi if.h.

## **Description**

This function fetches the error log. When an error occurs, call this function immediately before user processing ends.

## **Example**

```
#define USER DRIVER_ID
                        (0x00000001)
#define USER_LOG_MAX
                         (0x0000003f)
#define USER LOG ADR MAX (0x00001fff)
flash spi status t    ret = FLASH SPI SUCCESS;
flash_spi_info_t
                   Flash Info W;
                   buf1[128/sizeof(uint32 t)];
uint32 t
                              /* the buffer boundary (4-byte unit) */
Flash Info W.p data = (uint8 t *)&buf1[0];
ret = R FLASH SPI Write Data Page(FLASH SPI DEVO, &Flash Info W);
if (FLASH SPI SUCCESS != ret)
    /* Set last error log to buffer. */
   R FLASH SPI Log(USER DRIVER ID, USER LOG MAX, USER LOG ADR MAX);
   R FLASH SPI Close (FLASH SPI DEV0);
}
```

#### **Special Notes**

Incorporate the LONGQ FIT module separately.

Enable the option #define FLASH\_SPI\_CFG\_LONGQ\_ENABLE in r\_flash\_spi\_config.h. Also, enable #define xxx LONGQ ENABLE in the clock synchronous single master control software used by the specified device.

## R\_FLASH\_SPI\_1ms\_Interval()

This function calls the interval timer counter function of the clock synchronous single master control software. When using the DMAC or DTC, use a timer to call this function at 1 ms intervals.

#### **Format**

void R\_FLASH\_SPI\_1ms\_Interval(void)

#### **Parameters**

None

#### **Return Values**

None

#### **Properties**

Prototype declarations are contained in r\_flash\_spi\_if.h.

## Description

Increments the internal timer counter of the clock synchronous single master control software while waiting for the DMAC transfer or DTC transfer to finish.

## **Example**

```
void cmt_callback (void * pdata)
{
    uint32_t channel;
    channel = (uint32_t)pdata;
    if (channel == gs_cmt_channel)
     {
        R_FLASH_SPI_1ms_Interval();
     }
}
```

### **Special Notes**

User a timer or the like to call this function at 1 ms intervals.

In the example above, this function is called by a callback function that runs at 1 ms intervals.



## 4. Demo Projects

Demo projects include function main() that utilizes the FIT module and its dependent modules (e.g. r\_bsp). This FIT module includes the following demo projects.

## 4.1 rx65n\_rsk\_flash\_spi\_sample, rx65n\_rsk\_flash\_spi\_sample\_gcc

This is the sample application of FLASH SPI FIT module written for the Renesas RSKRX65N board. The program demonstrates how to use the APIs to control and use MX25L serial flash memory as a slave through clock synchronous single master control software is QSPI FIT module, operation as a master device.

## **Setup and Execution**

- Ensure driver support for channel 0 is enabled in r\_qspi\_smstr\_rx\_config.h: #define QSPI\_SMSTR\_CFG\_CH0\_INCLUDED
- 2. Build and download this sample application to the RSK board using the e2studio debugger.
- 3. Select the Renesas Virtual Debug Console view in e2studio to view printf information.
- 4. Run the application in the debugger.
- 5. Observe the version number of FLASH SPI module and ID of the serial flash memory print in the debug console window.
- 6. "Success!" is displayed in the debug console window.
- 7. If one of the operations fails "Failed." is displayed in the debug console window

## **Boards Supported**

RSKRX65N

# 4.2 rx671\_ek\_flash\_spi\_sample, rx671\_ek\_flash\_spi\_sample\_gcc

This is the sample application of FLASH SPI FIT module written for the Renesas EKRX671 board. The program demonstrates how to use the APIs to control and use AT25QF64 serial flash memory as a slave through clock synchronous single master control software is QSPIX memory mapped mode, operation as a master device.

### **Setup and Execution**

- Ensure driver support for channel 0 is enabled in r\_qspix\_rx\_config.h: #define QSPIX\_CFG\_USE\_CH0 (1)
- 2. Build and download this sample application to the EK board using the e2studio debugger.
- 3. Select the Renesas Virtual Debug Console view in e2studio to view printf information.
- 4. Run the application in the debugger.
- 5. Observe the version number of FLASH SPI module and ID of the serial flash memory print in the debug console window.
- 6. "Success!" is displayed in the debug console window.
- 7. If one of the operations fails "Failed." is displayed in the debug console window.

### **Boards Supported**

EKRX671



# 5. Appendices

# **5.1 Confirmed Operation Environment**

This section describes confirmed operation environment for the Flash SPI FIT module.

**Table 5.1 Confirmed Operation Environment (Rev.3.00)** 

Item	Contents		
Integrated development	Renesas Electronics		
environment	e <sup>2</sup> studio V7.3.0		
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V.3.01.00		
	Compiler option: The following option is added to the default settings of the		
	integrated development environment.		
	-lang = c99		
Endian	Big endian/little endian		
Revision of the module	Rev.3.00		
Board used	Renesas Starter Kit for RX113 (product No.: R0K505113xxxxxx)		
	Renesas Starter Kit for RX231 (product No.: R0K505231xxxxxx)		
	Renesas Starter Kit+ for RX64M (product No.: R0K50564Mxxxxxx)		
	Renesas Starter Kit for RX71M (product No.: R0K50571Mxxxxxx)		

**Table 5.2 Confirmed Operation Environment (Rev.3.01)** 

Item	Contents			
Integrated development	Renesas Electronics e <sup>2</sup> studio V7.3.0			
environment	IAR Embedded Workbench for Renesas RX 4.10.01			
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V.3.01.00 Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99			
	GCC for Renesas RX 4.08.04.201803			
	Compiler option: The following option is added to the default settings of the integrated development environmentstd=gnu99			
	IAR C/C++ Compiler for Renesas RX version 4.10.01			
	Compiler option: The default settings of the integrated development environment.			
Endian	Big endian/little endian			
Revision of the module	Rev.3.01			
Board used	Renesas Starter Kit+ for RX65N (product number.RTK500565Nxxxxxxx)			

# Table 5.3 Confirmed Operation Environment (Rev.3.02)

Item	Contents			
Integrated development	Renesas Electronics e <sup>2</sup> studio 2020-07			
environment	IAR Embedded Workbench for Renesas RX 4.14.01			
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V.3.02.00 Compiler option: The following option is added to the default settings of the integrated development environmentlang = c99			
	GCC for Renesas RX 8.03.00.202002 Compiler option: The following option is added to the default settings of the integrated development environmentstd=gnu99			
	IAR C/C++ Compiler for Renesas RX version 4.14.01 Compiler option: The default settings of the integrated development environment.			
Endian	Big endian/little endian			
Revision of the module	Rev.3.02			
Board used	Renesas Starter Kit+ for RX72N (product number.RTK5572Nxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxx			

# **Table 5.4 Confirmed Operation Environment (Rev.3.03)**

Item	Contents			
Integrated development	Renesas Electronics e <sup>2</sup> studio 2021-07			
environment	IAR Embedded Workbench for Renesas RX 4.20.01			
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V.3.03.00			
	Compiler option: The following option is added to the default settings of the integrated development environment.			
	-lang = c99			
	GCC for Renesas RX 8.03.00.202102			
	Compiler option: The following option is added to the default settings of the			
	integrated development environment.			
	-std = gnu99			
	IAR C/C++ Compiler for Renesas RX version 4.20.01			
	Compiler option: The default settings of the integrated development			
	environment.			
Endian	Big endian/little endian			
Revision of the module	Rev.3.03			
Board used	Renesas Starter Kit+ for RX671 (product number.RTK55671xxxxxxxxxxx)			

# **Table 5.5 Confirmed Operation Environment (Rev.3.10)**

Item	Contents			
Integrated development	Renesas Electronics e <sup>2</sup> studio 2022-04			
environment	IAR Embedded Workbench for Renesas RX 4.20.03			
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V.3.04.00			
	Compiler option: The following option is added to the default settings of the integrated development environment.			
	-lang = c99			
	GCC for Renesas RX 8.03.00.202204			
	Compiler option: The following option is added to the default settings of the			
	integrated development environment.			
	-std = gnu99			
	IAR C/C++ Compiler for Renesas RX version 4.20.03			
	Compiler option: The default settings of the integrated development environment.			
Endian	Big endian/little endian			
Revision of the module	Rev.3.10			
Board used	Renesas Starter Kit+ for RX65N (product number.RTK500565Nxxxxxx)			

# Table 5.6 Confirmed Operation Environment (Rev.3.20)

Item	Contents			
Integrated development	Renesas Electronics e <sup>2</sup> studio 2023-01			
environment	IAR Embedded Workbench for Renesas RX 4.20.03			
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V.3.04.00			
	Compiler option: The following option is added to the default settings of the integrated development environment.			
	-lang = c99			
	GCC for Renesas RX 8.03.00.202202			
	Compiler option: The following option is added to the default settings of the integrated development environment.			
	-std = gnu99			
	IAR C/C++ Compiler for Renesas RX version 4.20.03			
	Compiler option: The default settings of the integrated development environment.			
Endian	Big endian/little endian			
Revision of the module	Rev.3.20			
Board used	Evaluation Kit+ for RX671 (product number.RTK5EK671xxxxxxxxxxx)			

# Table 5.7 Confirmed Operation Environment (Rev.3.30)

Item	Contents			
Integrated development	Renesas Electronics e <sup>2</sup> studio 2023-04			
environment	IAR Embedded Workbench for Renesas RX 4.20.03			
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V.3.05.00			
	Compiler option: The following option is added to the default settings of the integrated development environment.			
	-lang = c99			
	GCC for Renesas RX 8.03.00.202305			
	Compiler option: The following option is added to the default settings of the integrated development environment.			
	-std = gnu99			
	IAR C/C++ Compiler for Renesas RX version 4.20.03			
	Compiler option: The default settings of the integrated development environment.			
Endian	Big endian/little endian			
Revision of the module	Rev.3.30			
Board used	Evaluation Kit+ for RX671 (product number.RTK5EK671xxxxxxxxxxx)			
	Renesas Starter Kit+ for RX65N (product number.RTK500565Nxxxxxx)			

### 6. Reference Documents

User's Manual: Hardware

The latest version can be downloaded from the Renesas Electronics website.

Technical Update/Technical News

The latest information can be downloaded from the Renesas Electronics website.

User's Manual: Development Tools

RX Family C/C++ Compiler CC-RX User's Manual (R20UT3248)

The latest version can be downloaded from the Renesas Electronics website.

# **Related Technical Updates**

Not applicable technical update for this module.



# **Revision History**

			Description
Rev.	Date	Page	Summary
2.32	Jan 18, 2016	<b>—</b>	First edition issued
2.33	Feb 02, 2016	1	In Target Device.
			Added "RX Family microcontrollers".
			Added "RX130", "RX23T" and "RX24T".
		26	Updated contents in 2.9 Adding the Driver to Your Project.
			Deleted "Using" in title of application notes.
2.34	Jul 31, 2017	19	Deleted r cgc rx in 2.2 Software Requirements.
3.00	Feb.20,2019	1	Added "RX72T".
0.00	. 5.5.25,25.6	6-9	Updated contents in 1.2.2 Operating Environment and Memory Sizes.
		10	In 1.3.1FIT Module–Related Application Notes.
			Deleted R01AN1914EJ
			Deleted R01AN2280EJ
			Added R01AN1827EJ
			Added R01AN1815EJ
			Added R01AN4548EJ
		16	Update contents in 1.5.3 Software Structure.
		17	Update contents in 1.5.4 Relationship Between Control Software and
			Clock Synchronous.
		20	2.2 Software Requirements
			Added r_memdrv_rx.
			Changed r_rspi_smstr_rx to r_rspi_rx.
		21-22	2.6 Compile Settings
			Deleted Marco.
			FLASH_SPI_CFG_DEVx_DRVIF_CH_NO
			FLASH_SPI_CFG_DEVx_MODE
			FLASH_SPI_CFG_DEVx_DMAC_CH_NO_Tx FLASH_SPI_CFG_DEVx_DMAC_CH_NO_Rx
			FLASH_SPI_CFG_DEVx_DMAC_INIT_PRIORITY_LEVEL_Tx
			FLASH_SPI_CFG_DEVx_DMAC_INIT_PRIORITY_LEVEL_RX
			FLASH SPI CFG DEVx BR
			FLASH SPI CFG DEVx BR WRITE DATA
			FLASH_SPI_CFG_DEVx_BR_READ_DATA
		25	Update contents in 2.9 Adding the Driver to Your Project.
3.01	May.20,2019	-	Update the following compilers
			GCC for Renesas RX
			IAR C/C++ Compiler for Renesas RX
		2	Added Target Compilers.
		2	Deleted R01AN1723 and R01AN1826 from Related Documents.
		6	Changed 1.2 Overview and Memory Size of APIs to 1.2 Overview of
			APIs. 1.2.2 Operating Environment and Memory Sizes, deleted.
		16	Added revision of dependent r_bsp module in 2.2 Software
		22.7	Requirements.
		20-21	2.8 Code Size, added.
		26	2.13 "for", "while" and "do while" statements: added
		33	3.4 R_FLASH_SPI_Set_Write_Protect(), fixed Example.

			Description
Rev.	Date	Page	Summary
3.01	May.20,2019	39	3.7 R_FLASH_SPI_Write_Data_Page(), fixed Example.
		42	3.8 R FLASH SPI Erase(), fixed Example.
		51	3.13 R_FLASH_SPI_Write_Configuration(), fixed Example.
		57	3.16 R_FLASH_SPI_Quad_Enable(), fixed Example.
		60	3.17 R_FLASH_SPI_Quad_Disable(), fixed Example.
		66	4.1 Confirmed Operation Environment, added.
3.02	Dec.10,2020	1	Added "RX72N".
	·	21	2.8 Code Size, amended.
		24	Changed Section 2.10 Adding the Driver to Your Project
		28-66	Deleted "Reentrancy" item on the API description page.
		68	Added Table 4.3 Confirmed Operation Environment (Rev.3.02).
		69	Changed Section 5 Reference Documents.
		Program	FLASH SPI FIT module fixed due to software failure.
		D	Description: A warning and linkage errors arise during building when using GPIO module firmware integration technology and MPC module firmware integration technology.  Conditions: 1. Use the integrated development environment CS+. 2. Serial Flash memory FIT module general-purpose I/O port control is performed by both of the following FIT modules. GPIO module Firmware Integration Technology MPC module Firmware Integration Technology  Corrective action: Please use FLASH_SPI FIT module Rev3.02.  Corresponding tool news number: R20TS0609
		Program	Description: When setting the device capacity of r_flash_spi to 1G-bit in the SC component, a build error occurs.  Conditions: Set the device capacity of r_flash_spi to 1G-bit in the SC component and build.  Corrective action: Please use FLASH_SPI FIT module Rev3.02.

			Description
Rev.	Date	Page	Summary
3.02	Dec.10,2020	Program	FLASH_SPI FIT module fixed due to software failure.
			_
			Description:
			On RX72M/RX72N/RX66N, if the device port of
			r_flash_spi_pin_config.h is set to "H", "K", "M", "N", or "Q", a build
			error will occur.
			Conditions:
			Set FLASH_SPI_CS_DEV0_CFG_PORTNO or
			FLASH_SPI_CS_DEV1_CFG_PORTNO to one of "H", "K", "M", "N",
			and "Q" to build.
			Corrective action:
			Please use FLASH_SPI FIT module Rev3.02.
3.03	Nov.30,2021	1	Added "RX671 Group (QSPIX)".
		5	Added "QSPIX FIT module" in Overview.
		7	Update contents in 1.3.1 FIT Module–Related Application Notes.
		7	1.4 Using Serial Flash Memory Module, added.
		11-16	Modified the picture format.
		17	Added r_qspix_rx in 2.2 Software Requirements.
		21-22	2.8 Code Size, amended.
		68	Added Table 4.4 Confirmed Operation Environment (Rev.3.03).
3.10	Jun.30,2022	19	2.6 Compile Settings
			Added new macros
			#define FLASH_SPI_CS_DEVx_CFG_PORTNO
			#define FLASH_SPI_CS_DEVx_CFG_BITNO
		21	2.8 Updated FIT module version, and compilers' version
		69	4.1 Confirmed Operation Environment: Added Table for Rev.3.10.
		Drogram	
		Program	Added new macros to specify the ports used for SS#  Fixed issues of wrong conditional expression in the if statement.
			Set PORTX as the default port assigned to SS#.
3.20	Mar.16,2023	1, 6, 20,	Added support for AT25QF641B-SHB.
0.20	Wai. 10,2020	31-50, 71,	Added Support for A120Q1 041B-01B.
		74	
		1, 5, 7, 17	Added RSCI FIT module.
		18	2.6 Compile Settings:
			Added new macros
			#define FLASH_SPI_CFG_DEVx_AT25QF
		21	2.8 Updated FIT module version, and compilers' version.
		32-35, 58-	3. API Functions:
		63, 67-70	Added new API functions
			R_FLASH_SPI_Read_Status2()
			R_FLASH_SPI_Read_Status3()
			R_FLASH_SPI_Write_Status()
			R_FLASH_SPI_Write_Status2() R_FLASH_SPI_Write_Status3()
			R_FLASH_SPI_Read_Data_Security_Page()
			R FLASH SPI Write Data Security Page()
			N_1 LAO11_01 1_Wille_Data_Geouilty_Fage()

		Description		
Rev.	Date	Page	Summary	
3.20	Mar.16,2023	42	3. API Functions: amended	
			Added notes for R_FLASH_SPI_Read_Data	
		83	4.1 Confirmed Operation Environment:	
			Added Table for Rev.3.20.	
		Program	Added support for AT25QF641B-SHB with Indirect Access Mode of QSPIX	
			Added support for RSCI and QSPIX Memory Mapped Mode.	
			Removed the processing related to other unsupported flash devices.	
3.30	Jun.15,2023	13	Added " AT25QF family" in 1.6.3 Structure Software	
		24	Deleted the description of FIT configurator from "2.10 Adding the	
			Driver to Your Project"	
		81	Added "4. Demo Project"	
		85	5.1 Confirmed Operation Environment:	
			Added Table for Rev.3.30.	
		Program	Deleted the description of FIT configurator.	
			Updated and added new demo project	

## General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

- 1. Precaution against Electrostatic Discharge (ESD)
  - A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.
- 2. Processing at power-on
  - The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.
- 3. Input of signal during power-off state
  - Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.
- 4. Handling of unused pins
  - Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.
- 5. Clock signals
  - After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.
- 6. Voltage application waveform at input pin
  - Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between  $V_{IL}$  (Max.) and  $V_{IH}$  (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between  $V_{IL}$  (Max.) and  $V_{IH}$  (Min.).
- 7. Prohibition of access to reserved addresses
  - Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.
- 8. Differences between products
  - Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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